



Second Quarter FY 2021 Quarterly Update

Infineon Technologies AG
Investor Relations



Infineon at a glance

Addressing long-term high-growth trends



IoT (edge comp., data center, 5G, sensing, connectivity)



electro-mobility



assisted driving, autonomous driving



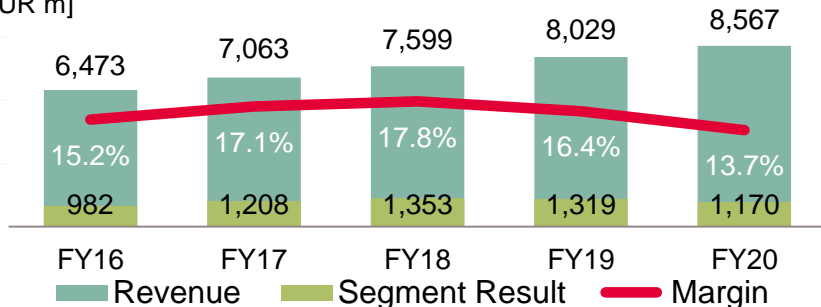
energy efficiency, renewables, EV infrastructure



security

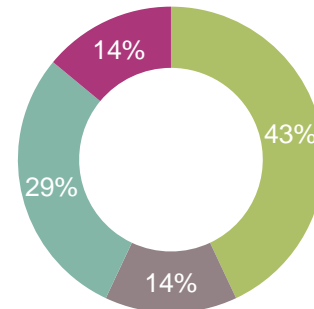
Financials

[EUR m]



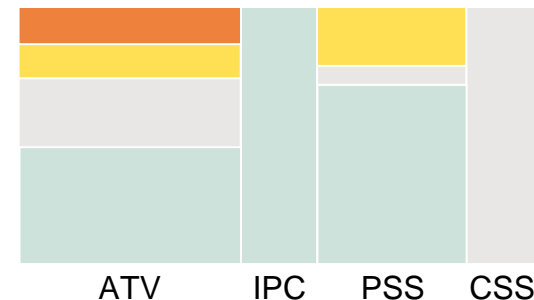
Illustrative aggregated FY20 revenue by segment

- Automotive (ATV)
- Industrial Power Control (IPC)
- Power & Sensor Systems (PSS)
- Connected Secure Systems (CSS)



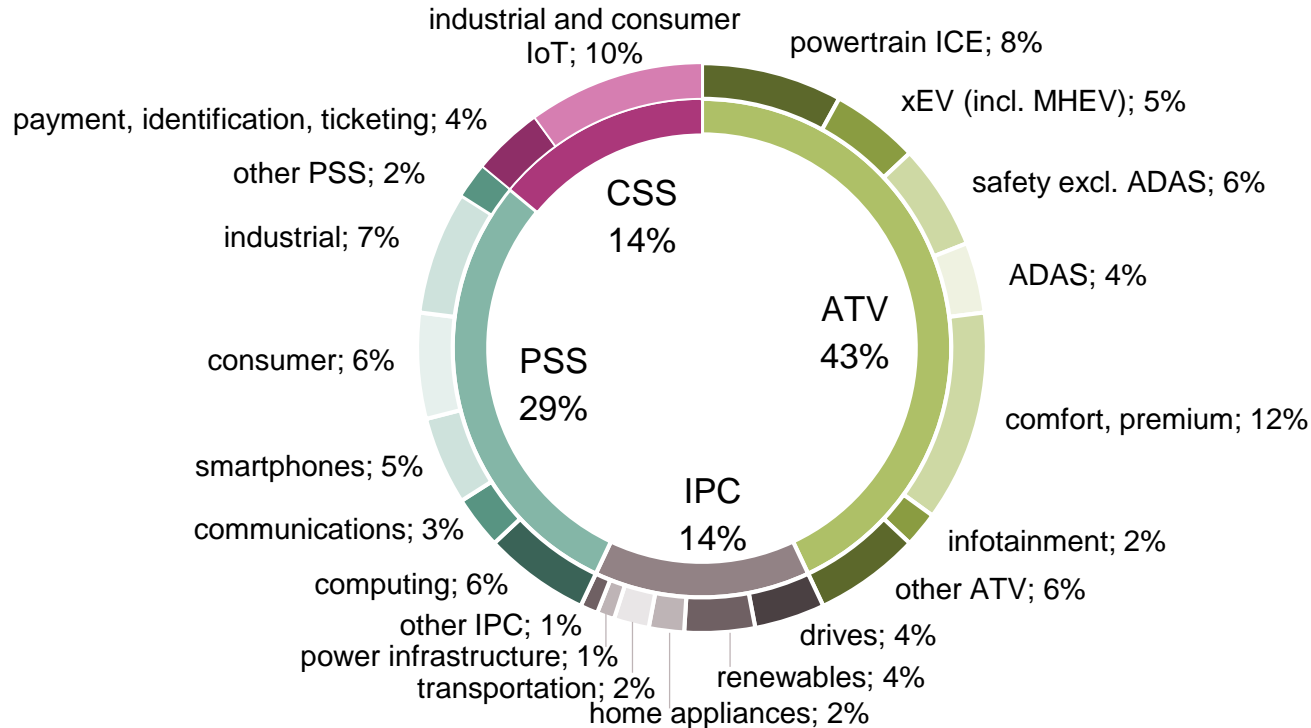
Illustrative aggregated FY20 revenue by product category

- ~5% memories for specific applications
 - ~10% RF & sensors
 - ~30% embedded control and connectivity
 - ~55% power semi-conductors
- of total revenue



Illustrative aggregated FY20 revenue including contribution from Cypress of ~€1,900m from 1 Oct 2019 through 30 Sep 2020

Illustrative aggregated FY20 revenue of ~€9,600m by target application

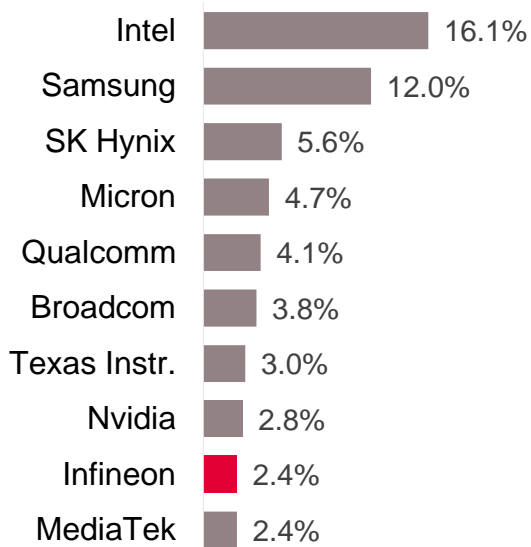


Infineon is a global top-10 player, #1 in power semiconductors, and ranked #3 in the overall microcontroller market



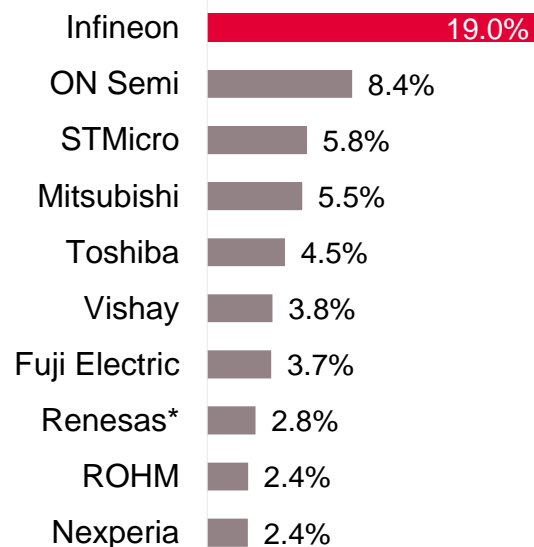
Semiconductor suppliers

2020 total market: \$473bn¹⁾



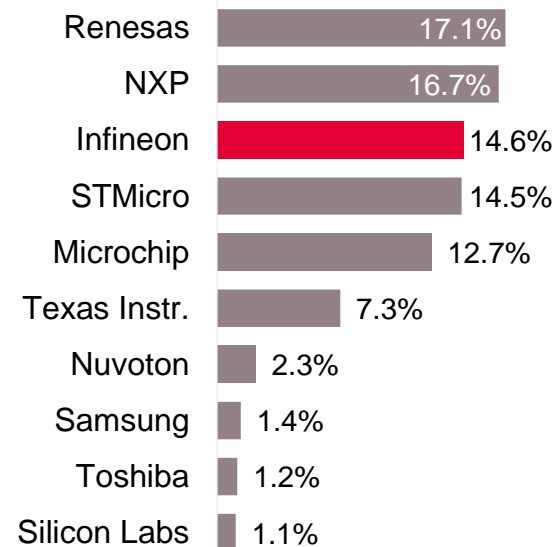
Power discretes and modules

2019 total market: \$21.0bn²⁾



MCU suppliers

2020 total market: \$17.3bn¹⁾



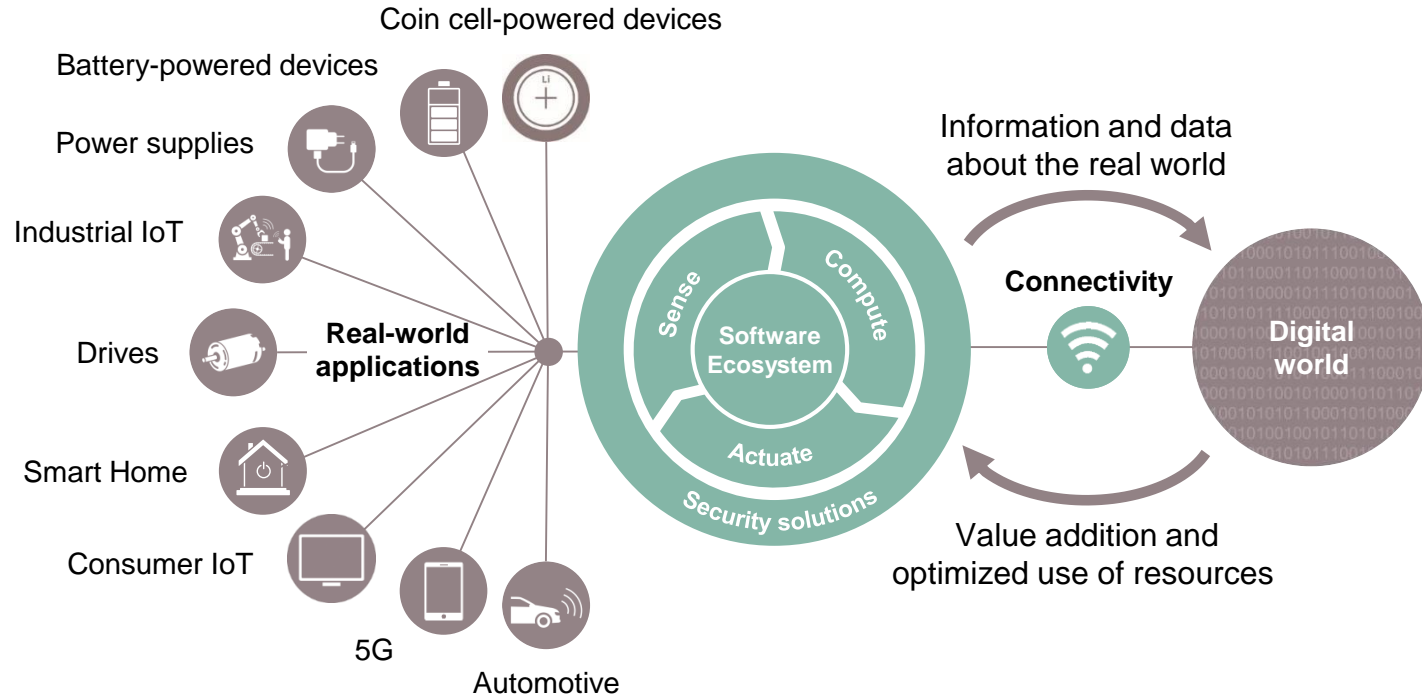
* Renesas acquired Integrated Device Technology in March 2019. Both companies were combined as Renesas in the 2019 ranking.

1) Based on or includes research from Omdia: *Annual 2001-2020 Semiconductor Market Share Competitive Landscaping Tool – Q4 2020*. March 2021.

2) Based on or includes research from Omdia: *Power Semiconductor Market Share Database – 2020*. September 2020.

Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk.

Infinion offers a unique portfolio that links the real and the digital world



Sense: sensors

Compute: microcontrollers, memories

Actuate: power semiconductors

Connectivity: Wi-Fi, Bluetooth, USB

Outlook for Q3 FY21 and FY21

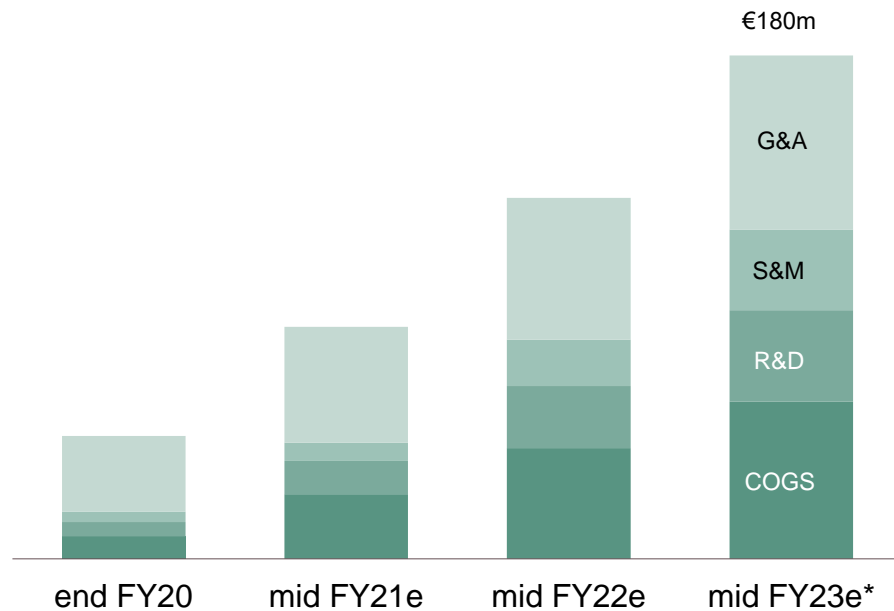
	Outlook Q3 FY21*	Outlook FY21*
Revenue	€2.6bn – €2.9bn	~ €11.0bn +/- 3% (prev.: ~ €10.8bn +/- 5%)
Segment Result Margin	At the mid-point of the revenue guidance: ~ 18%	At the mid-point of the revenue guidance: ~ 18% (prev.: ~17.5%)
Investments in FY21		~ €1.6bn
D&A in FY21		€1.5bn – €1.6bn**
Free cash flow in FY21		> €1.2bn (prev.: > €800m)

* Based on an assumed average exchange rate of \$1.20 for €1.00

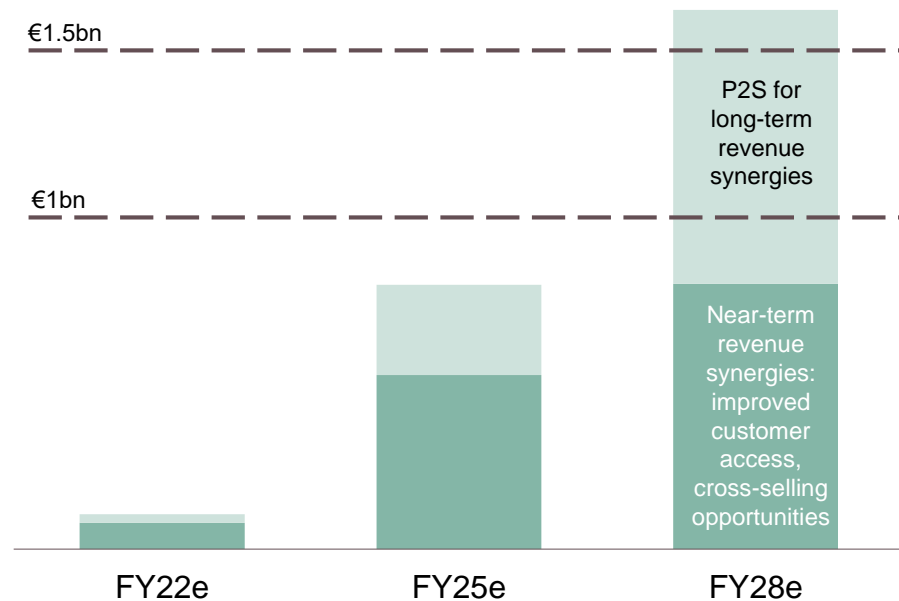
** Including the effects of the purchase price allocation for Cypress and, to a lesser extent, International Rectifier

Reaping of synergies on track

Planned ramp-up of cost synergies






Planned ramp-up of revenue synergies



Expected integration and restructuring costs equivalent to ~1x cost synergies one-off over time.

* Expected cost synergies of €180m p.a. gradually ramping up over approximately three years after closing (16 April 2020).

Infineon's through-cycle target operating model

		Target Operating Model
		Infineon financial performance to approach targets as Cypress integration progresses
Revenue growth		9%+
Segment Result Margin		19%
Investment-to-sales		13%

Design-win at an Asian OEM: Infineon semiconductors worth more than €500 in an upper mid-range EV platform with SAE L2 automation



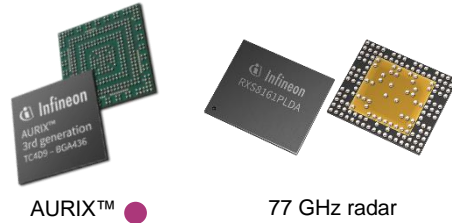
Category

Major products

Main applications (comprising 14x AURIX™)



ADAS

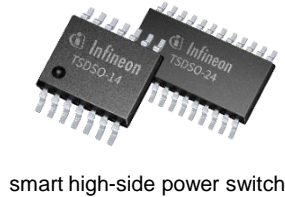


AURIX™

77 GHz radar



comfort, premium,
standard safety,
infotainment



smart high-side power switch



EV drivetrain



CoolSiC™ MOSFET Module

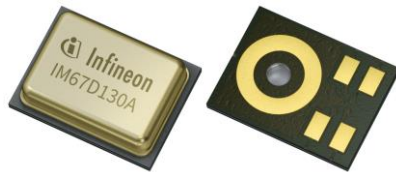
sensor fusion	mid-range radar	front camera	parking system	remote vehicle assistance
ABS	HVAC	PTC heater	integrated central gateway unit	full redundant EPS
black box system	audio, video, navigation	oil pump	interior lamp	integrated electronic brake
electronic gear shifter	seat heater	water pump	charge lamp	drive video record system
SiC-based main inverter	high-voltage BMS	inverter gate board	OBC / Low DC-DC converter	vehicle control unit

Infinion introduced industry's first AEC-Q103-qualified high-performance XENSIV™ MEMS microphone for automotive applications



Infinion expands the application range of its MEMS microphones into automotive

**XENSIV™ IM67D130A
MEMS microphone**

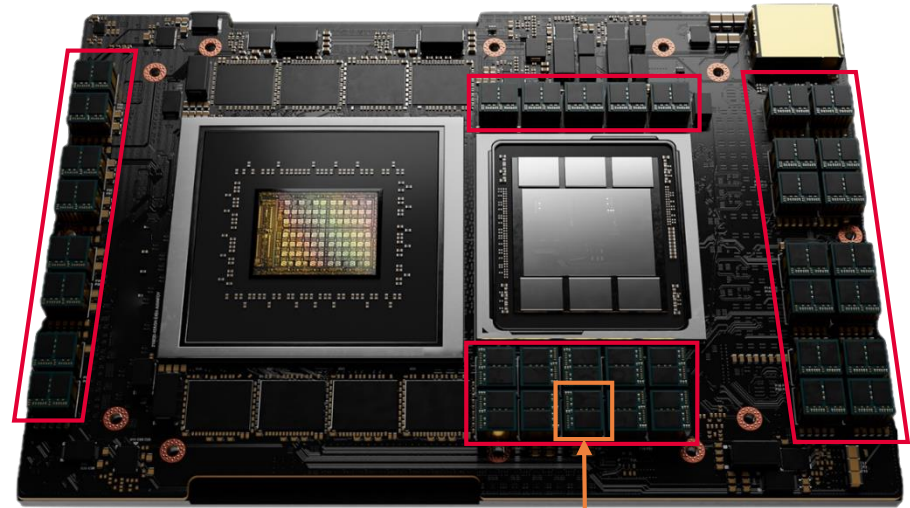


- › The newly launched IM67D130A MEMS microphone enables the use of sound as a complementary sensor for
 - improved speech recognition
 - advanced driver assistance systems
- › The outstanding acoustic characteristics allow the microphone to capture distortion-free audio signals in loud environments for
 - interior applications: hands-free systems, emergency calls, in-cabin communication, active noise cancellation
 - exterior applications: siren detection, road condition recognition

Infinion provides leading-edge DC-DC power conversion for high-performance acceleration boards

Next-generation accelerator boards are driving the need for ultra-high density and robust power conversion solutions

- › Exponential increase in compute power driven by AI training and high-performance compute (HPC) systems resulting in power consumption of > 1 kW per board
- › 15% to 25% higher DC-DC power semiconductor content with every xPU generation
- › Infineon's robust and high-efficiency power management solutions are optimized to support high-performance xPUs, ASICs and SoCs with superior power density
- › Infineon's high-density Smart Power Stages enable system designs with highest power density and quality



Courtesy: a leading CPU, GPU, and AI accelerator manufacturer

Infineon high-density 90 A Smart Power Stage
in 4 mm x 6 mm package

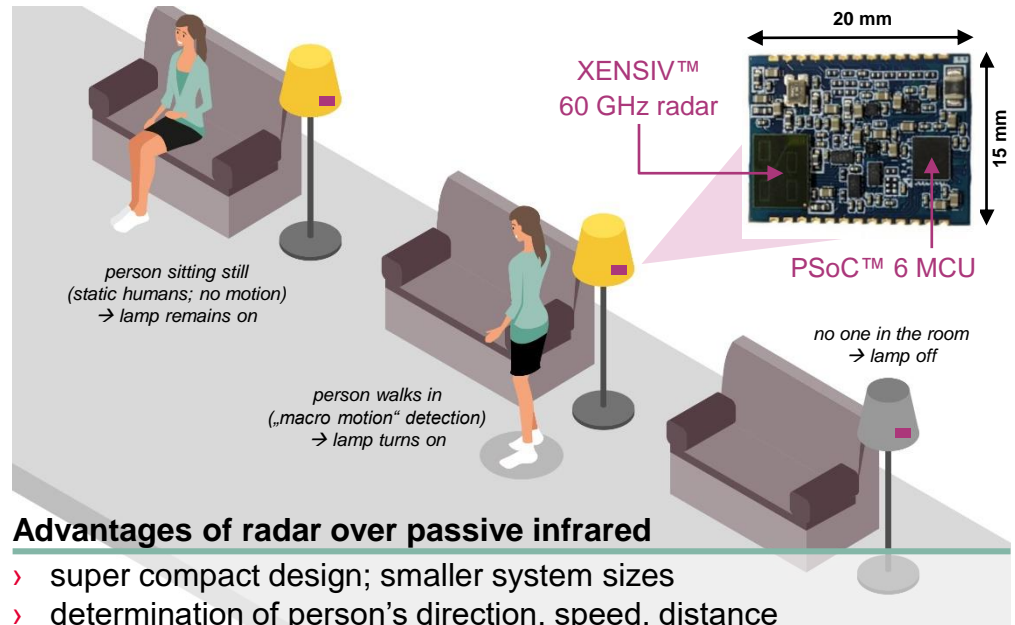
Infineon radar turn-key solution addresses IoT market via combining XENSIV™ 60 GHz radar and highly integrated PSoC™ 6 MCU

Key facts

- › Infineon offers complete turn-key solution comprising of sensor, MCU and software libraries (apps, SDKs)
- › BLE functionality monolithically integrated on MCU
- › Radar sensor remotely controlled via smartphone app
- › IoT target applications: entrance control or presence detection for smart home and smart building
- › Radar solutions are anonymous and therefore respecting privacy
- › First orders for presence detection received from several Asian customers
- › optionally: radar solution can perfectly be combined with Infineon's XENSIV™ PAS CO2 sensor for air quality monitoring



Example application: presence detection



Advantages of radar over passive infrared

- › super compact design; smaller system sizes
- › determination of person's direction, speed, distance
- › programmable; can flexibly be adapted to the target application
- › higher accuracy; more precise measurements of detected objects
- › depending on the antenna configuration: position of a moving object

Infinion's new AIROC™ Wi-Fi 6/6E and Bluetooth® 5.2 solutions bring reliable, high-performance connectivity to smart homes



Key facts

- › Infineon is expanding its AIROC™ wireless portfolio of high-performance, reliable and secured offerings with combined Wi-Fi 6/6E and Bluetooth® 5.2 combo capabilities
- › Key advantages of the new solution include:
 - Doubled wireless coverage range compared to Wi-Fi 4 and 5
 - 40% more coverage than typical Wi-Fi 6/6E solutions
 - Over 20% power savings, enabling longer battery life
 - Improved connection robustness with enhanced interference mitigation
 - Multi-layer security protections enabling a higher level of security for IoT applications

Selected target applications



streaming devices



game consoles



smart speakers



infotainment



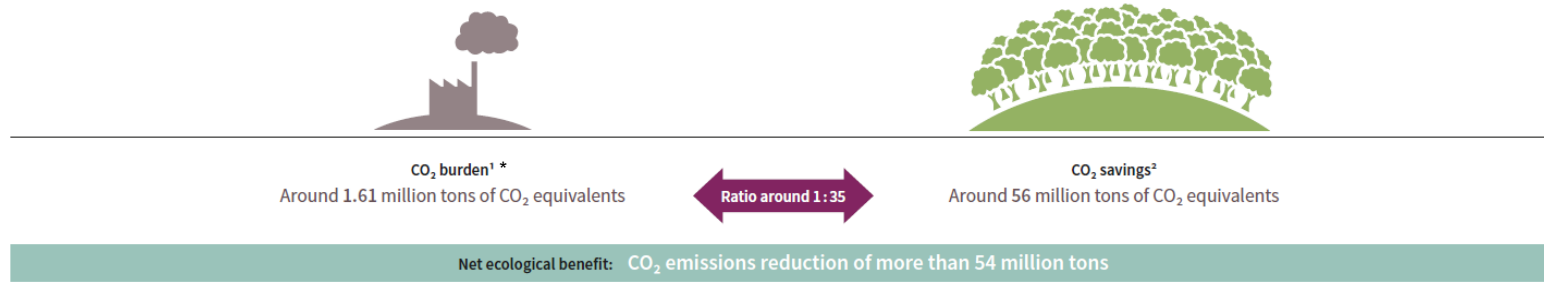


ESG: targets and achievements



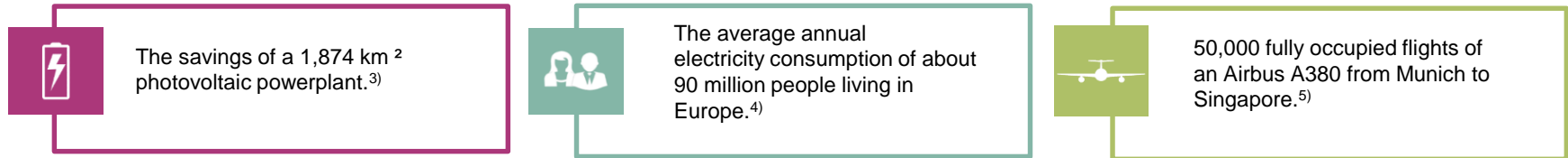
Our products and innovations together with an efficient production are key elements to deal with climate change

We contribute a CO₂ reduction of more than 54 million tons



* The increase in the burden of CO₂ equivalents can mainly be explained by including manufacturing service providers for the first time into the calculation

Our net ecologic CO₂ benefit is equal to...



For explanatory notes see appendix

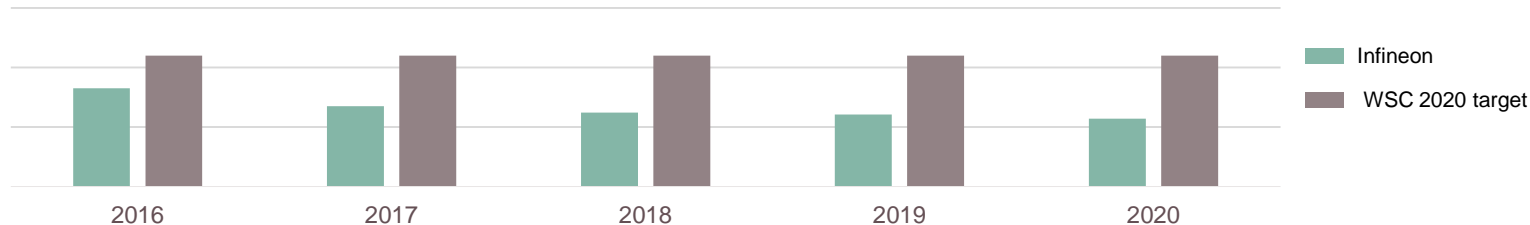
Infineon will become carbon-neutral by 2030

70% CO₂ emissions reduction target in 2025 (scope 1 and 2 emissions)

1. Avoiding direct emissions and further reducing energy consumption
2. Purchasing green electricity with guarantees of origin for unavoidable emissions
3. Compensate the smallest part by certificates that combine development support and CO₂ abatement

Abatement of Perfluorinated Compounds (PFC's)¹ is one of the most important measures avoiding direct emissions.










Normalized PFC emissions rate in tons of CO₂ equivalent per square meter wafer



Historically, Infineon's normalized emission rate has been below WSC 2020 target of 2.2 in tons of CO₂ per square wafer

1) Namely perfluorinated and polyfluorinated carbon compounds, sulfur hexafluoride (SF₆) and nitrogen trifluoride (NF₃)

External recognitions confirm our engagement in contributing to a sustainable society

		Rating/Score	Scale	Date
	MSCI ESG	AA	CCC to AAA	02/2021
	CDP	B climate scoring B water scoring	F to A	12/2020
	Ecovadis	98 th percentile “Gold” award	0 to 100	11/2020
	Dow Jones Sustainability Index	81 Dow Jones Sustainability™ World and Europe Index listing	0 to 100	11/2020
	Ethibel Sustainability Index Excelece Europe”	Index member	-	05/2020
	ISS ESG Corporate Rating	B- Prime Status	D- to A+	01/2021
	FTSE4Good Index	Index member	-	07/2020
	Euronext Vigeo Eurozone 120 Index Euronext Vigeo Europe 120 Index	Indices member	-	06/2020
	Sustainalytics	77 “Outperformer” level	0 to 100	06/2020

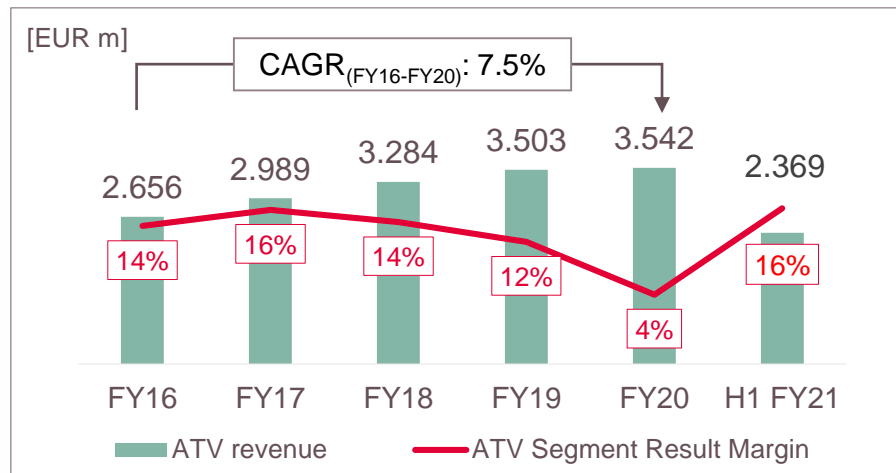


Automotive

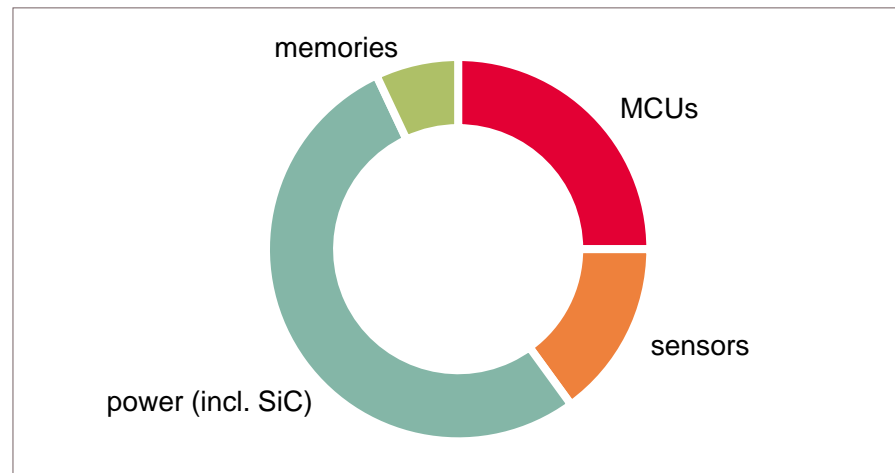


ATV at a glance

ATV revenue and Segment Result Margin



FY20 revenue split by product group



Key customers



Market outlook for ATV division's target applications

Applications

Market Outlook for CY21



- › Y-Y recovery with unit growth at mid-teens %
- › Unit growth momentum in CY21 hindered by semiconductor shortages; the shortage is expected to last a few more months
- › Continued uncertainties related to market development mainly due to COVID-19 pandemic



- › Incentives and CO₂ regulations should keep demand high
- › Improving consumer sentiment around sustainability theme
- › Steady investments in EV charging infrastructure further lowers reservation towards EVs

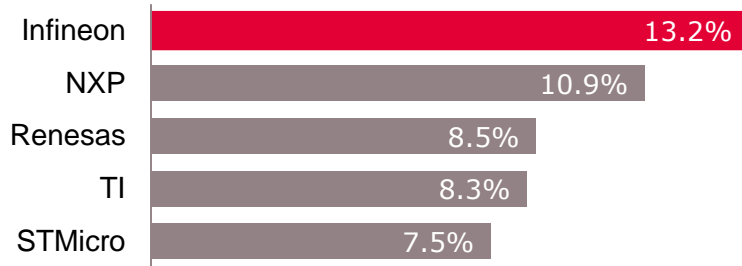


- › Further increase in L1 and L2 penetration expected
- › L2+ shipments still at the initial phase

Infiniteon's top market position is built on system competence based on an industry-leading product portfolio

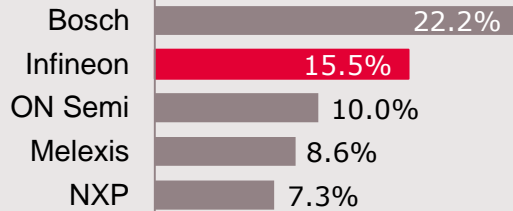


Automotive semiconductors (2020 total market: \$35.0bn)

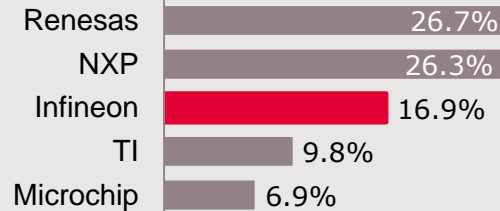


- › Strengthened #1 position; increasing distance to #2
- › #1 in power semiconductors
- › Undisputed #1 in automotive NOR Flash memory ICs
- › #2 position in sensors
- › Solid #3 position in microcontrollers due to strong demand in AURIX™, TRAVEO™ and PSoC™ families

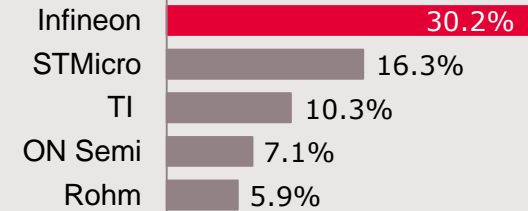
Sensors



Microcontrollers



Power semiconductors



Strategy Analytics: Automotive Semiconductor Vendor Market Shares. April 2021.



Electro-mobility



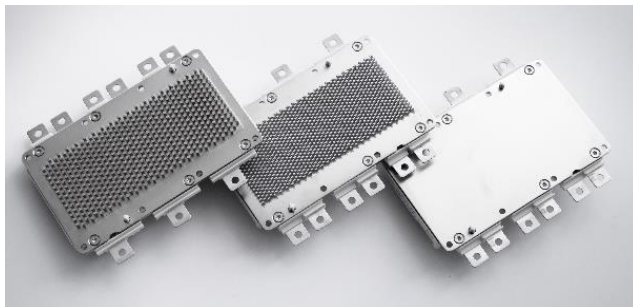
Infineon provides leading-edge power module technology to top-selling Chinese NEV models



NIO: EC6



Scalable Infineon HybridPACK™ Drive portfolio



XPeng: P5



GAC Trumpchi: Aion S EV



- › > 20 BEV platforms in production with Infineon HybridPACK™ Drive
- › > 1m pieces shipped with an unparalleled quality performance
- › Available with Si and SiC chips
- › Scalable module portfolio meets cost-performance sweet spots between 120 kW and 250 kW
- › Optimized versions for 400 V and 800V battery voltage

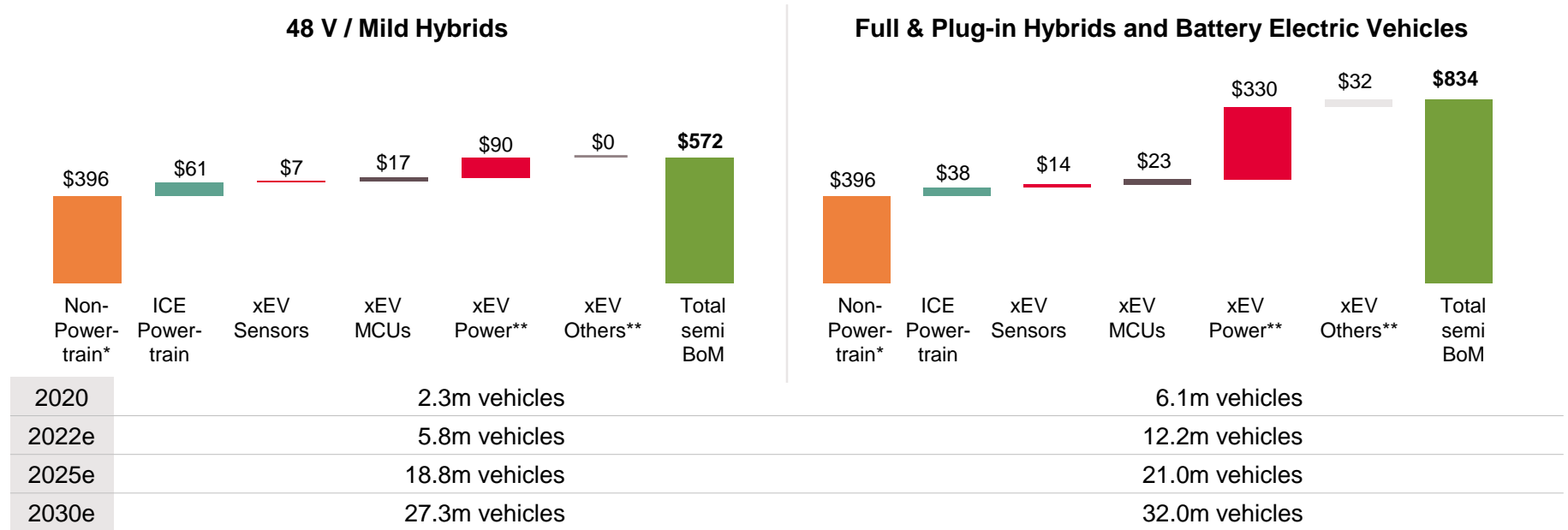
SAIC: MG EZS EV



The incremental content of power semiconductors in xEV is a significant opportunity for Infineon



2020 average xEV semiconductor content by degree of electrification



* Non-Powertrain: average semiconductor content in body, chassis, safety and infotainment application segments

** "power" includes voltage regulators and ASIC; "others" include opto, small signal discretes, memory

Sources: Infineon; based on or includes content supplied by IHS Markit, Automotive Group: *Alternative Propulsion Forecast*. July 2020;
Strategy Analytics: *Automotive Semiconductor Demand Forecast 2018-2027* and *Automotive Sensor Demand 2018-2027*. July 2020

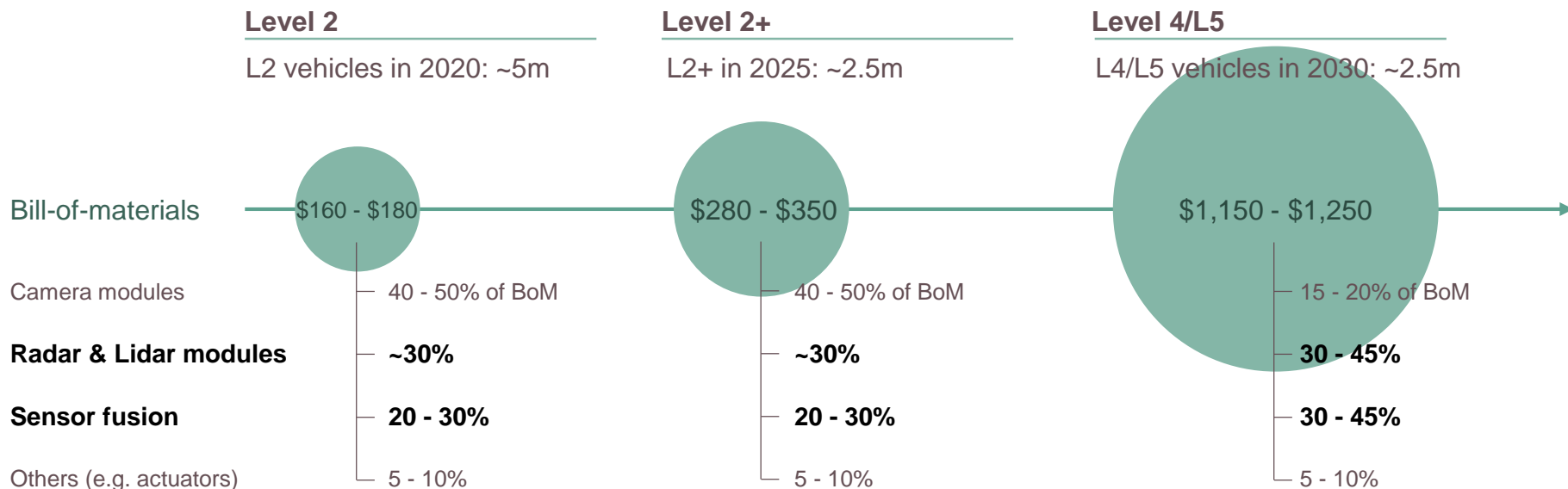


Automated Driving



Radar/Lidar modules and sensor fusion will grab the lion's share of semiconductor BoM in ADAS/AD-equipped cars

Incremental average semiconductor content per car by level of automation at the given years



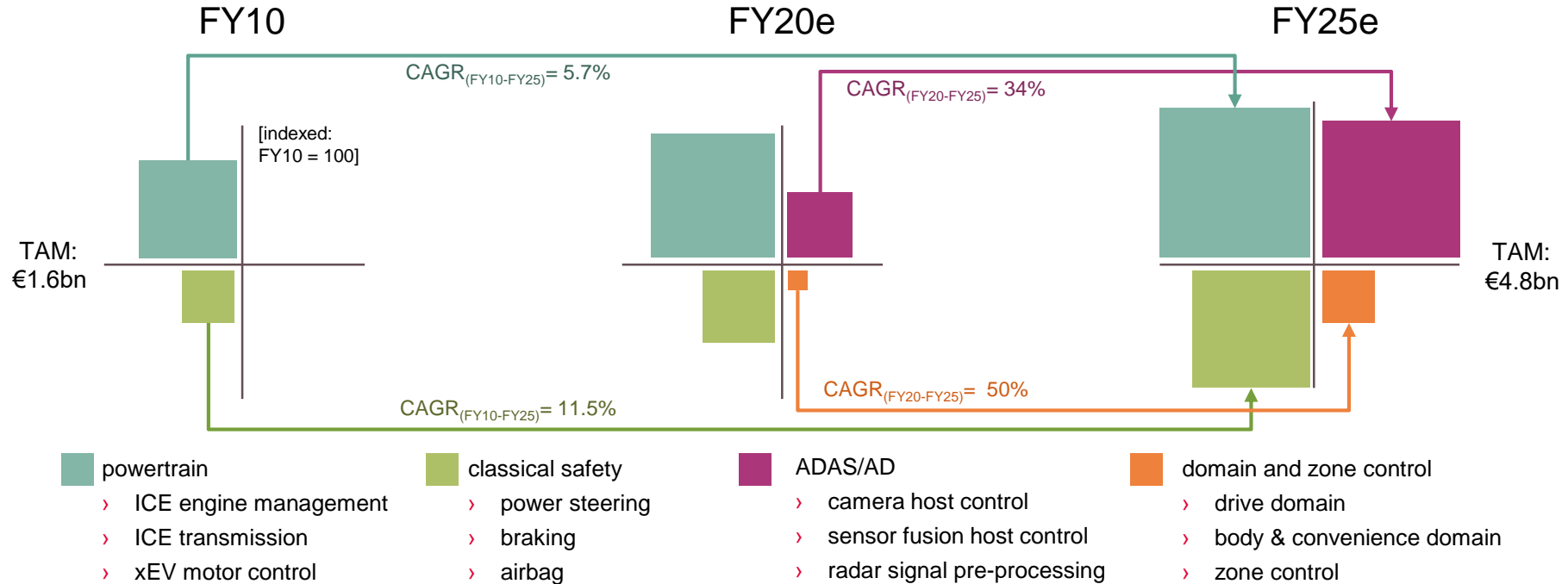
BoM contains all type of semiconductors (e.g. radar modules include μ C); sensor fusion does not include memory. BoM are projected figures for the respective time frame

Sources: Strategy Analytics: *Automated Driving Semiconductor Market Estimate*. August 2020; Infineon.

The Infineon AURIX™ μ C family has become the first-choice automotive architecture for high-growth and safety-critical applications



Infineon AURIX™ revenue development over time



Sources: Infineon; Strategy Analytics: *Automotive Semiconductor Demand Forecast*. February 2020. Covering Infineon target markets; excl. body, comfort, infotainment.

Strong microcontroller footprint in next-generation high-volume platforms

OEM platform #1:

- › 14 MCUs (+ NOR Flash + Wi-Fi)
- › start of production: end of CY20

Engine control module AURIX™ TC38x	Braking AURIX™ TC39x	AD fusion standard AURIX™ TC39x	Instrument cluster NOR Flash S26KS512
Drivetrain control module AURIX™ TC23x	Airbag AURIX™ TC23x	AD fusion high-end AURIX™ TC39x	Infotainment module 89359 (Wi-Fi / Bluetooth)
Transmission control module AURIX™ TC27x	Electric power steering AURIX™ TC27x	Central AD decision module AURIX™ TC39x	Central AD module NOR Flash S70FL01G S25FL512 S25FS512
Automatic gear shifter module AURIX™ TC23x	Automatic sway bar AURIX™ TC23x	Secure gateway module AURIX™ TC39x	
Electronic slip differential AURIX™ TC23x	Map driver assistance AURIX™ TC39x		

OEM platform #2:

- › 20 MCUs
- › start of production: CY22

Engine management AURIX™ TC38x	Braking AURIX™ TC38x	AD fusion standard AURIX™ TC39x	Cluster TFT module FCR4 MB9DF125
Diesel engine management AURIX™ TC39x	Airbag AURIX™ TC37x	AD fusion high-end AURIX™ TC39x	8" rear-seat entertainment TrueTouch TMA78
Transmission control module AURIX™ TC38x	Electric power steering AURIX™ TC36x	Front camera AURIX™ TC37x	10" navigation module TrueTouch TMA1036
Inverter PHEV AURIX™ TC38x	Suspension CVC AURIX™ TC38x	Radar domain processing AURIX™ TC39x	Climate, gearshift MMI FR CY91xxx
Door module FR MB91520	Alarm system module FR MB91F520	Digital instrument cluster Traveo I S6J332	Head light module FR MB91F525

Infineon heritage

Cypress heritage



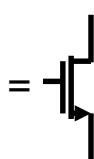
Infineon's Power Strategy



Infineon's portfolio covers the entire range of power and frequency

What is a power switch?



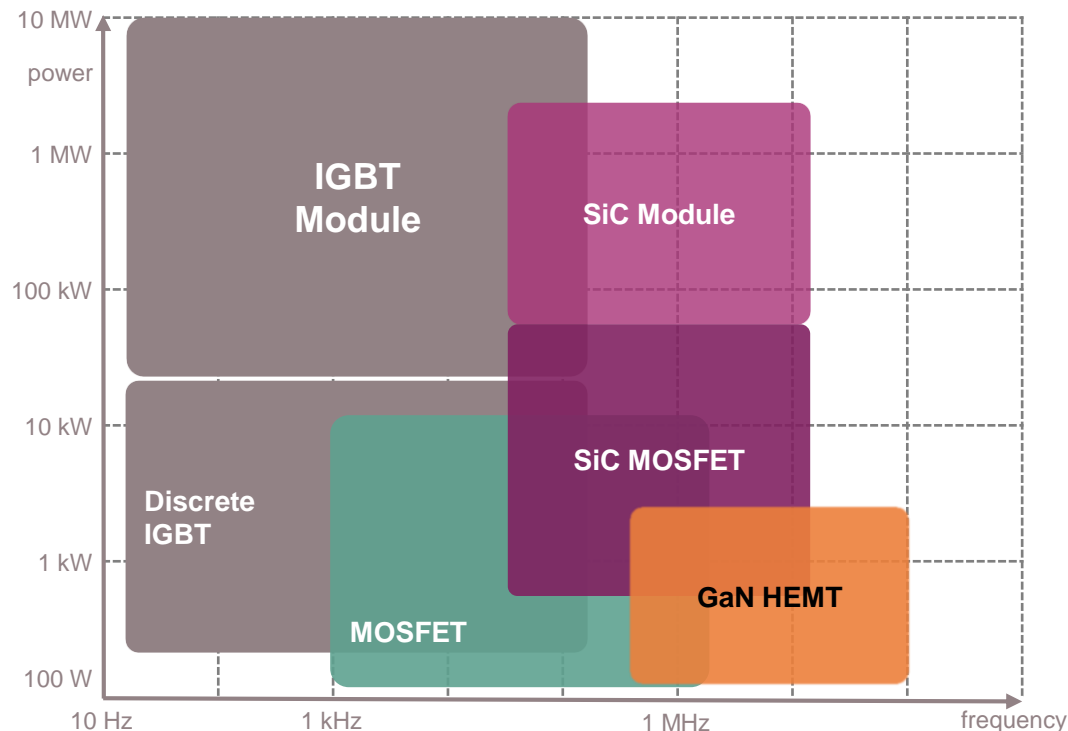
=  When turned on
→ current flows

When turned off
→ current is blocked

What counts?

- > Losses in on-state ($R_{DS(on)}$)
- > Heat dissipation
- > Max. switching frequency
- > Die size
- > Package size (form factor)

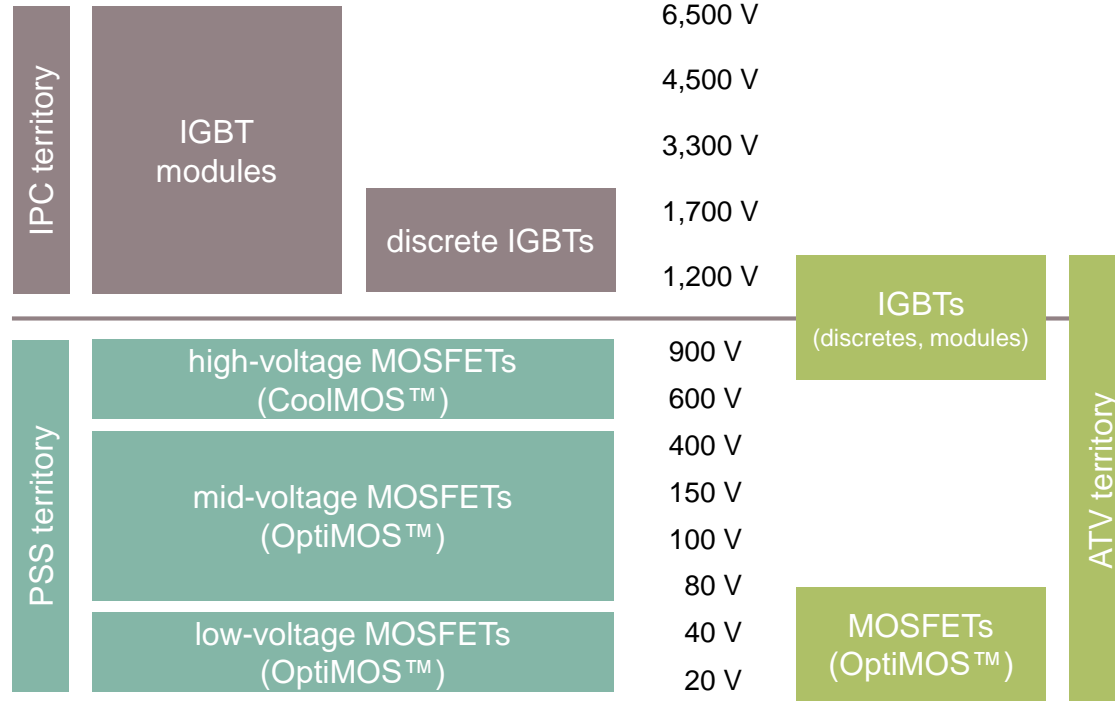
How are power switches categorized?



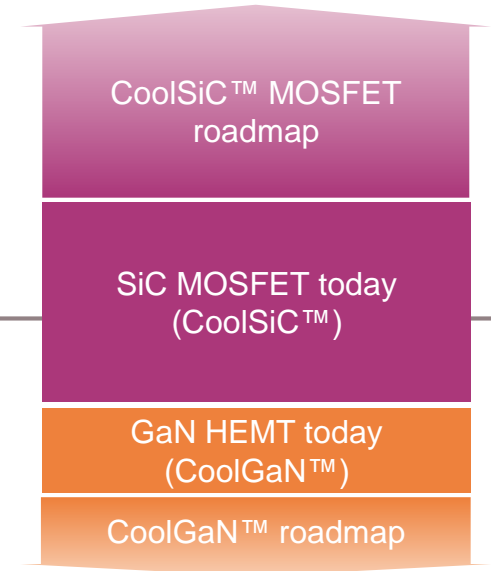
Infiniteon's discrete power portfolio* is basically separated by voltage classes



Silicon-based power switches



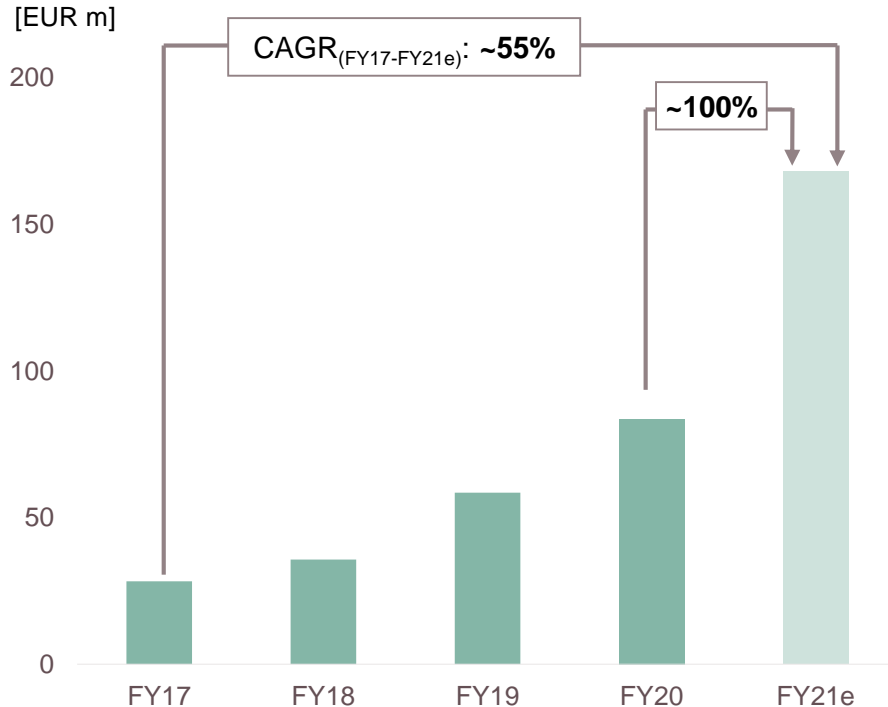
Compound semiconductors



* excluding drivers and control ICs

Raised forecast: doubling the revenue in FY21 – more than half of the incremental growth contributed by automotive

Industrial and automotive applications driving the growth







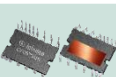





**~200 different CoolSiC™
products**

**~3,000 total active customers
including distribution**



Strong CoolSiC™ portfolio expansion: by packages and by voltages

Broadest and best-in-class SiC portfolio

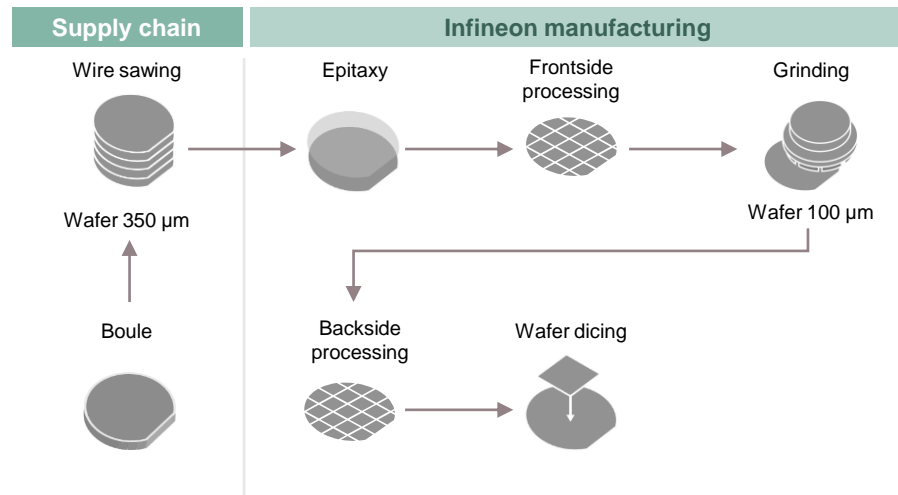
	Industrial						Automotive grade			
package options voltages	CoolSiC™ Diode	CoolSiC™ Hybrid		CoolSiC™ MOSFET			CoolSiC™ Diode	CoolSiC™ Hybrid	CoolSiC™ MOSFET	
	Discrete	Discrete	Module	Discrete	IPM	Module	Discrete	Discrete	Discrete	Module
										
600 V										
650 V										
1200 V										
1700 V										
Continuous expansion of portfolio										

Traditional wire sawing wastes ~3/4 of the raw material

Current status of SiC device manufacturing

The supplier cuts the boule into 350 μm thick wafers thereby losing almost half of the material as kerf. The resulting wafers are processed and ground to ~100 μm before finishing them. Thereby losing another half of the material.

→ ~3/4 of raw material lost

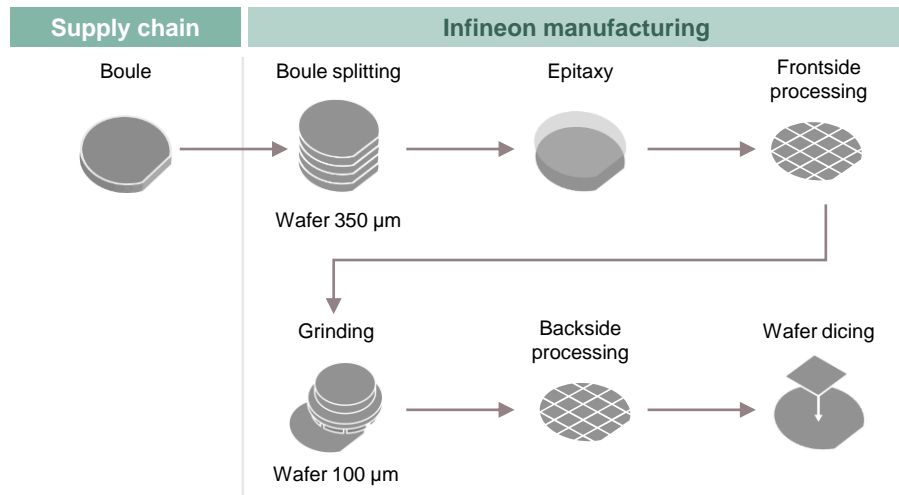


The kerf and grinding consume ~75% of the raw material

Phase 1: boule splitting in volume prod. starting FY22

We source boules and use our splitting technology to cut it into wafers. The process is kerf-free and therefore losses are minimal. The resulting 350 μm thick wafers are processed according to the current process flow.

→ Raw material losses reduced by half



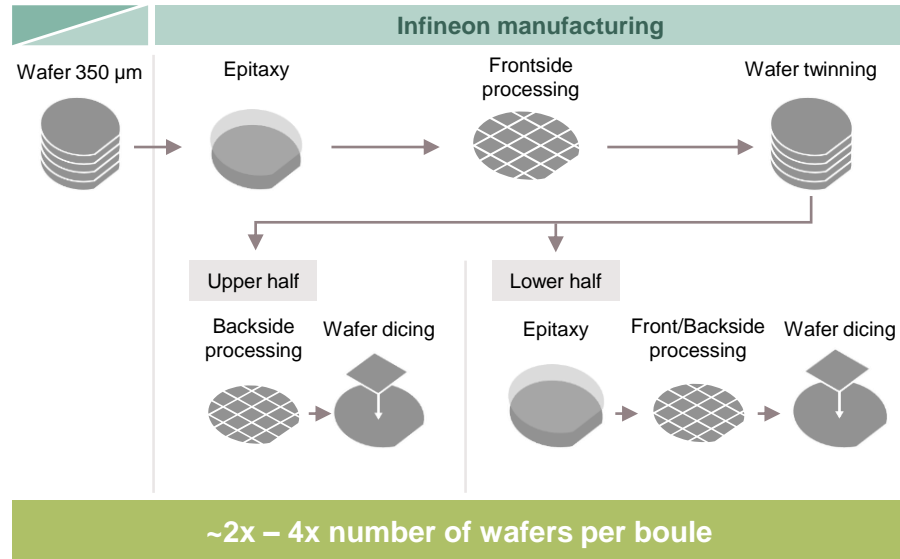
~2x number of wafers per boule compared to wire sawing

Boule splitting plus wafer twinning or advanced boule splitting quadruples output out of a given boule

Phase 2: wafer twinning

The starting material are either wafer from the phase 1 boule splitting process or sourced wafer. The 350 μm thick wafer is processed and instead of grinding it down to 100 μm the lower part is split off and processed again.

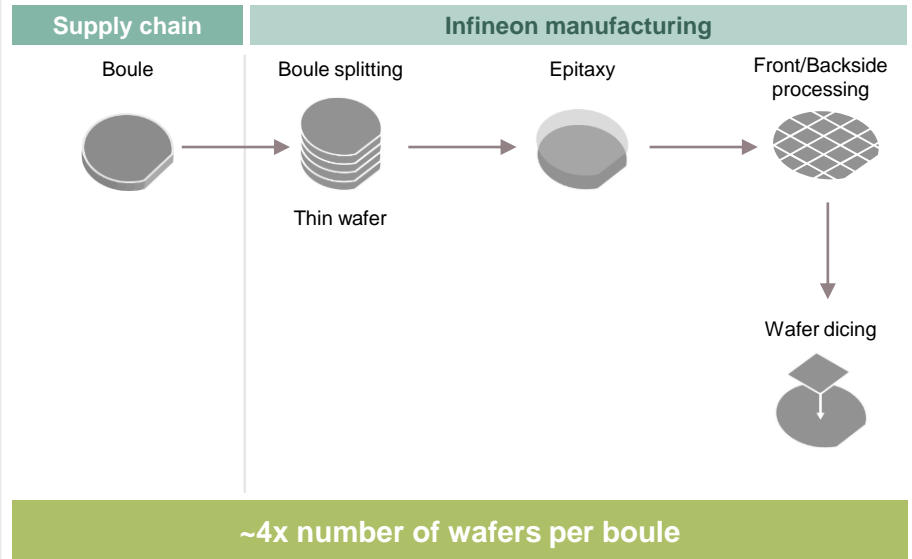
→ Combining boule and wafer twinning → minimal raw material losses



Phase 3: advanced boule splitting

The advanced boule splitting results in thin wafers that can be processed directly.

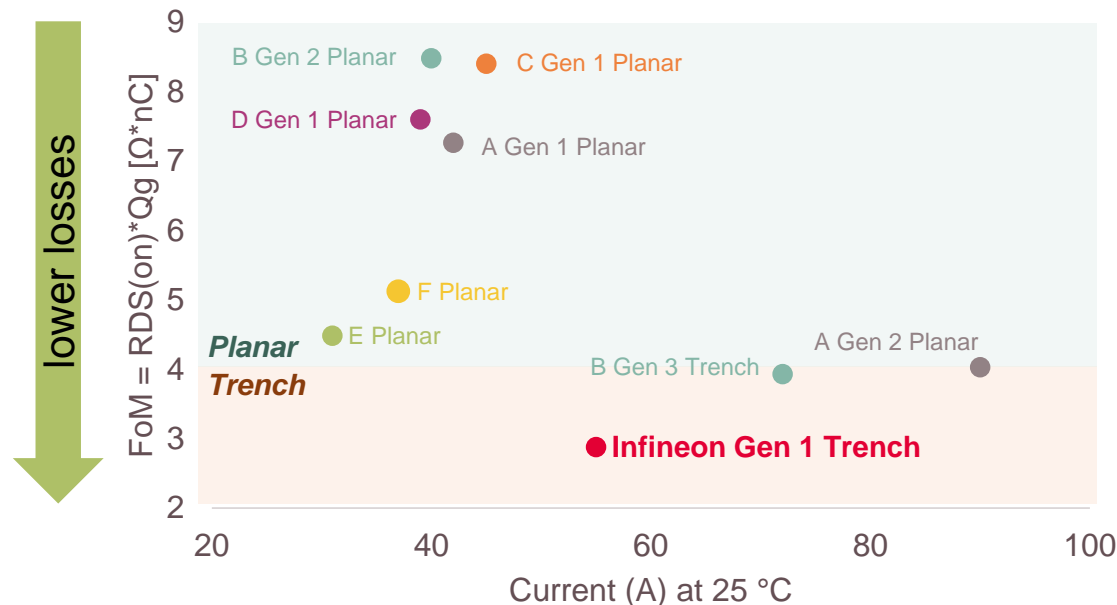
→ Most efficient process with minimal raw material losses



Second generation (2nd Gen.) CoolSiC™ Trench MOSFET will increase the addressable market

1st Gen. with lowest losses is the leading technology today

2nd Gen. will expand the lead



- › 2nd Gen. CoolSiC™ Trench MOSFET is in advanced development phase
- › Enhanced power handling capability by 25% – 30%
- › Enhanced safe operating area without compromising quality
- › Enabling SiC in further high volume applications

2nd Gen. CoolSiC™ Trench MOSFET will significantly enlarge the market size for SiC MOSFETs

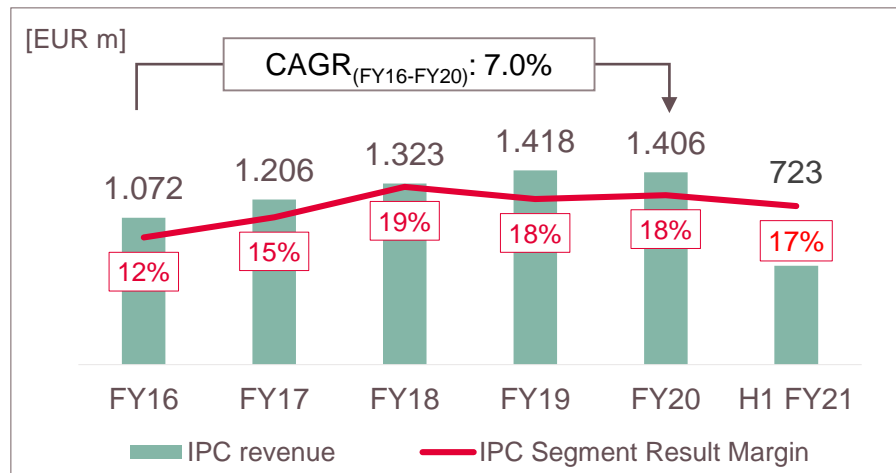


Industrial Power Control

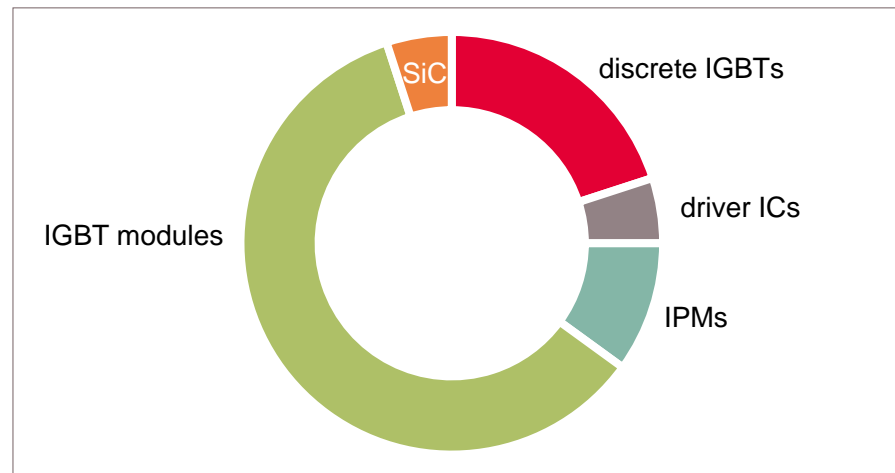


IPC at a glance

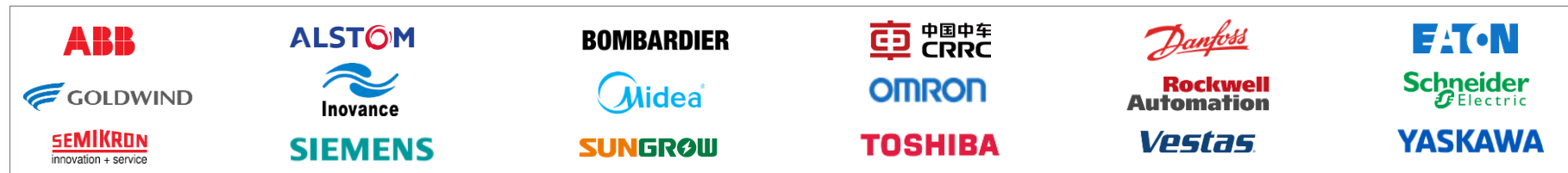
IPC revenue and Segment Result Margin









FY20 revenue split by product group



Key customers



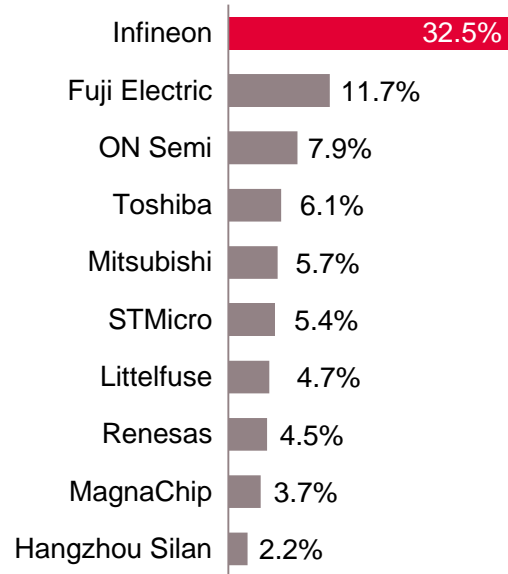
Market outlook for IPC division's target applications

Applications (% of FY20 segment revenue)	Market Outlook for CY21	
<div>Automation and Drives</div> <div>~30%</div>		<ul style="list-style-type: none"> Industrial Drives recovering in high single digits with demand growing mainly in GC region
<div>Renewables</div> <div>~24%</div>		<ul style="list-style-type: none"> Wind: installations forecasted to increase to all-time-high PV: market forecast continuously corrected upward
<div>Home appliance</div> <div>~16%</div>		<ul style="list-style-type: none"> Catch-up of delayed purchases and energy efficiency incentive programs will drive growth
<div>Transportation</div> <div>~13%</div>		<ul style="list-style-type: none"> Diminished COVID-related travel activities caused further push-out of construction of passenger trains and e-Busses
<div>Power Infrastructure</div> <div>~9%</div>		<ul style="list-style-type: none"> Growing demand in EV charging infrastructure, Industrial UPS and energy storage systems Delays in Transmission & Distribution projects
<div>Others</div> <div>8%</div>		<ul style="list-style-type: none"> Growth driven by general market recovery

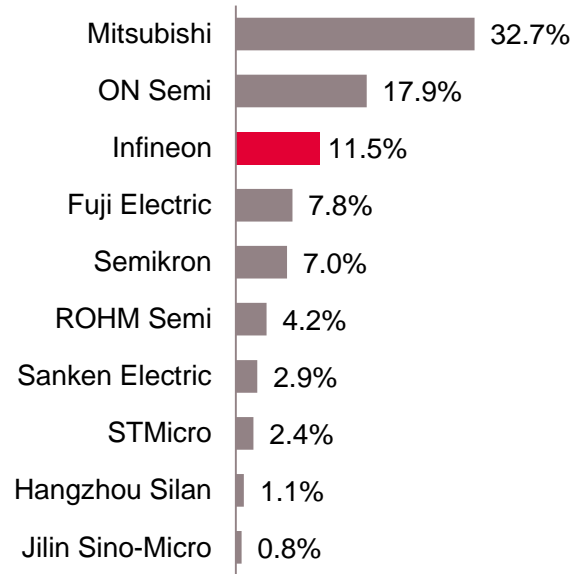
Clear leader in discrete IGBTs and IGBT modules; fostering position in IPMs



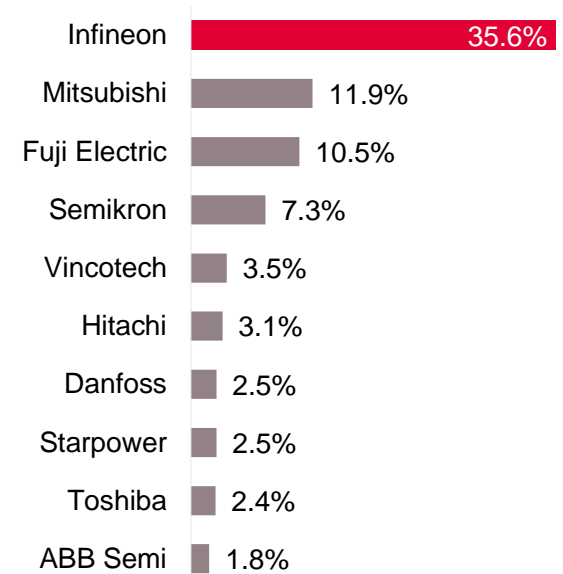
Discrete IGBTs 2019 total market: \$1.44bn



IPMs 2019 total market: \$1.59bn



IGBT modules¹⁾ 2019 total market: \$3.31bn



¹⁾ Including standard (non-integrated) IGBT modules and power integrated modules (PIMs) / converter inverter brake (CIB) modules
Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020*. September 2020

Infineon serves all applications in the field of renewable energy

Onshore



- › Application: Full Converter & Partial/DFIG* converter based wind turbine
- › Output: 1 MW – 6 MW
- › Power semi content: €2,000 - €3,250 per MW

Offshore



- › Application: Full Converter based wind turbine
- › Output: 3 MW – 14 MW
- › Power semi content: €3,250 - €3,500 per MW

HVDC**



- › Application: HVDC - VSC
- › Output: 100 MW – 4 GW
- › Power semi content: €5,200 - €18,000 per MW

String inverter



- › Application: residential, commercial and utility-scale PV plants
- › Output: 1 kW – 200 kW
- › Power semi content: €2,500 – €5,000 per MW

Central inverter

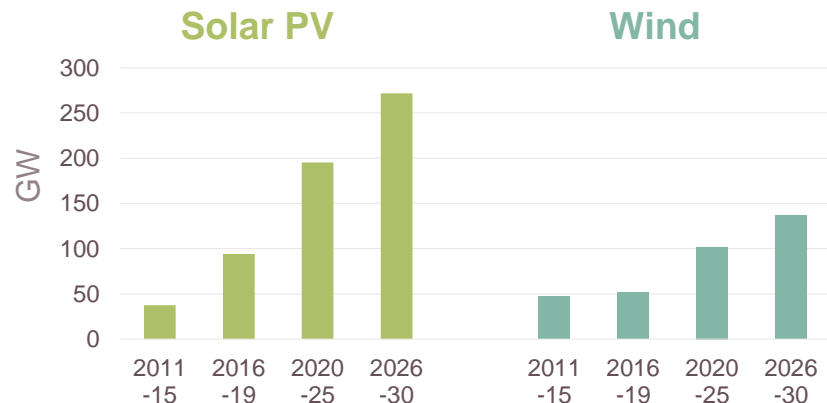


- › Application: utility-scale PV plants
- › Output: 600 kW – 1,250 kW
- › Power semi content: €2,000 – €3,000 per MW

*DFIG – Doubly fed induction generator ** HVDC - High-voltage direct current transmission

We are the #1 semiconductor enabler of renewable energies

Average annual solar PV and wind capacity additions*



Source: World Energy Outlook 2020, Average annual solar PV and wind capacity additions in the Sustainable Development Scenario to 2030 p. 109

All leading renewable energy players are our customers*

PV inverter

- 1 | Huawei
- 2 | Sungrow
- 3 | SMA
- 4 | TBEA Sunoasis
- 5 | Wuxi Sineng
- 6 | ABB
- 7 | Kstar
- 8 | Goodwe
- 9 | Growatt
- 10 | Power Electr.

Wind

- | | |
|----------------------|---|
| ✓ 1 Siemens/Gamesa | ✓ |
| ✓ 2 Vestas | ✓ |
| ✓ 3 Goldwind | ✓ |
| ✓ 4 GE | ✓ |
| ✓ 5 Enercon | ✓ |
| ✓ 6 Envision | ✓ |
| ✓ 7 Nordex | ✓ |
| ✓ 8 Senvion | ✓ |
| ✓ 9 United Power | ✓ |
| ✓ 10 Mingyang | ✓ |

Enabling Technologies



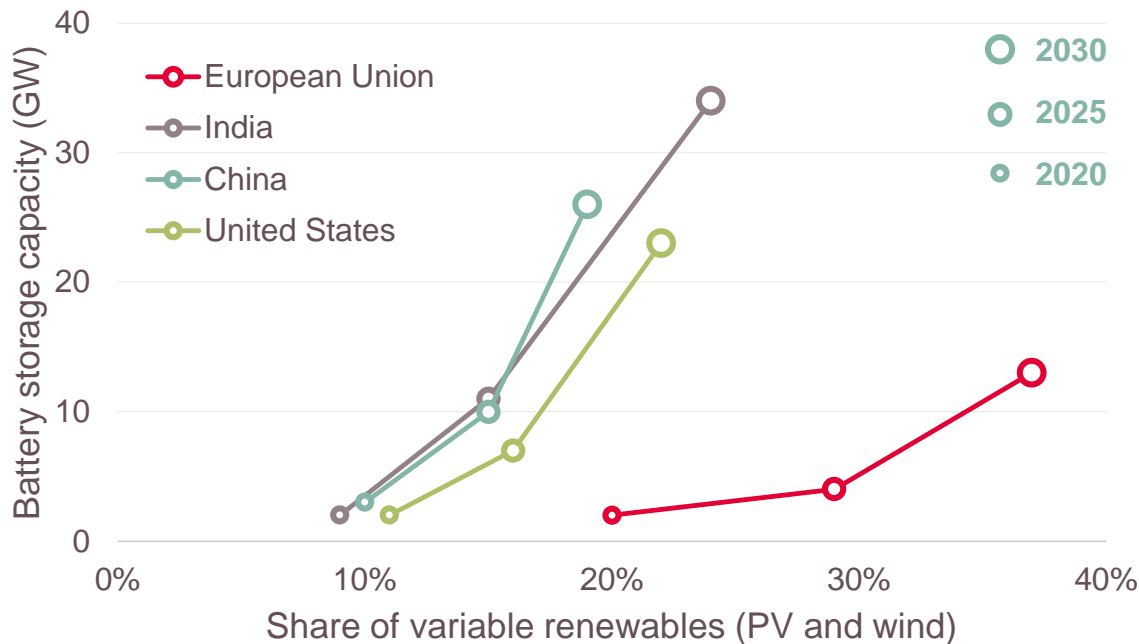
- > Reduces System Size
- > Reduced power losses up to 50% compared to a traditional IGBT



- > Increased lifetime of IGBT Modules
- > Highest reliability for remote places

Energy storage is essential to further deploy decentral and renewable energy generation

Battery storage capacity and share of variable renewables¹⁾



Key drivers

- › **Decentralization** of power generation
- › **Peak shaving** of energy generation and energy consumption
- › **Limited capacity** and flexibility of today's grids
- › **Reduction of standby cost** of fossil power plants

~€3,200 of power semiconductor content per MW of installed energy storage capacity²⁾

1) International Energy Agency: *World Energy Outlook 2020*, p. 248; variable renewables consist of solar and wind energy.

2) Infineon estimate

What comes next?

Mid- to long-term structural growth opportunities

Core



new material



EV charging



collaborative robots

Adjacent



solar pumps



energy storage



eDelivery vehicles

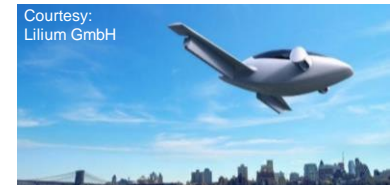
New area



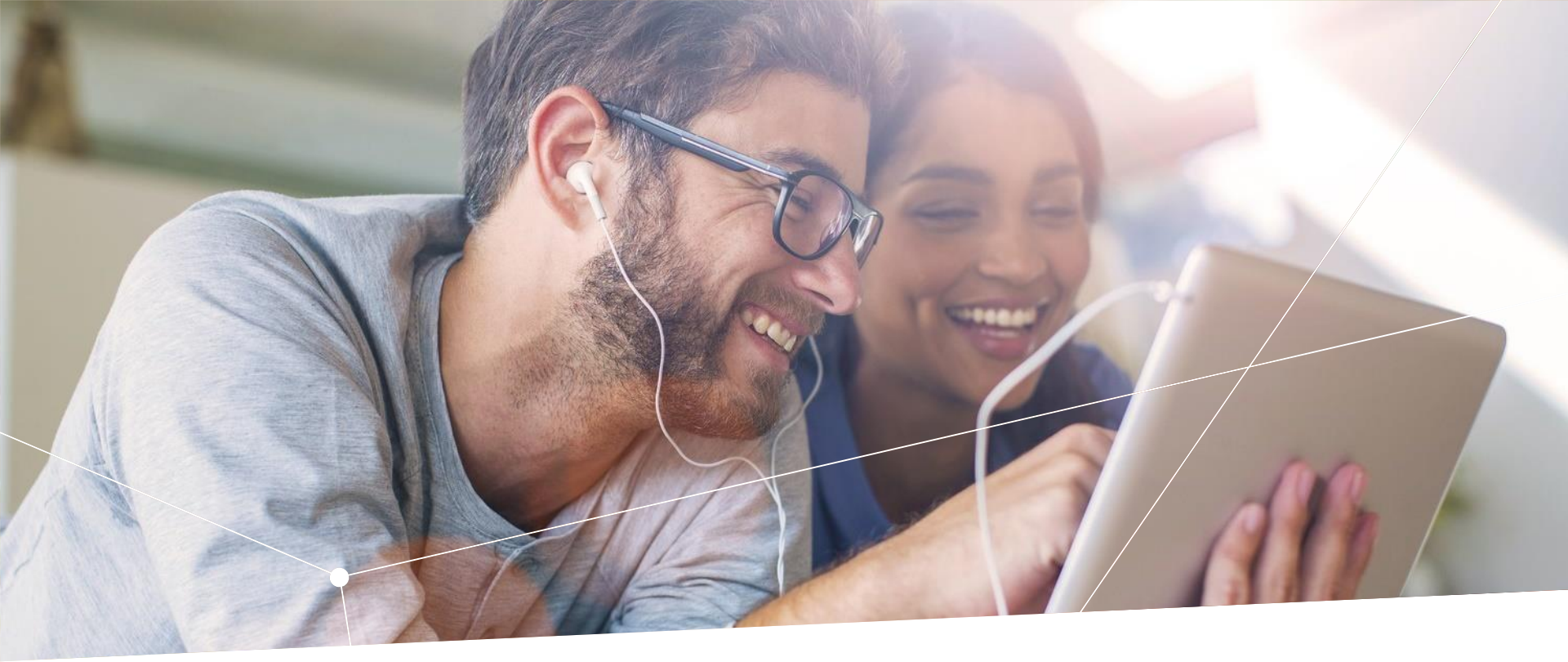
fuel cell



eMarine



eAviation

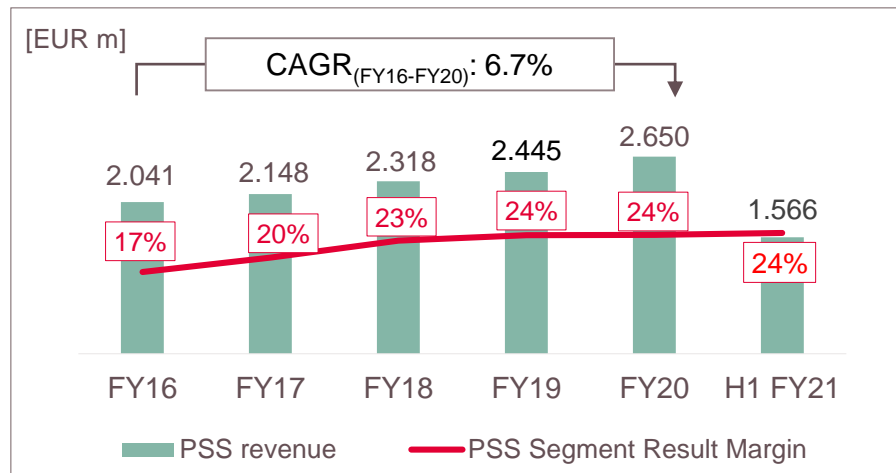


Power & Sensor Systems

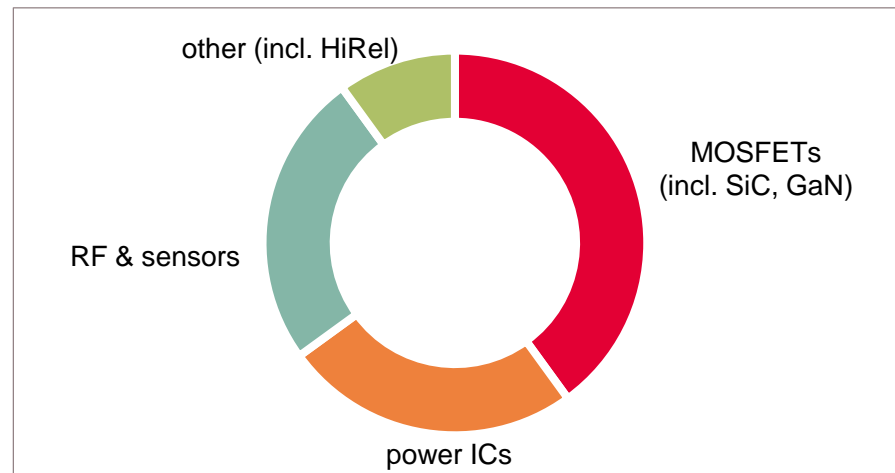


PSS at a glance

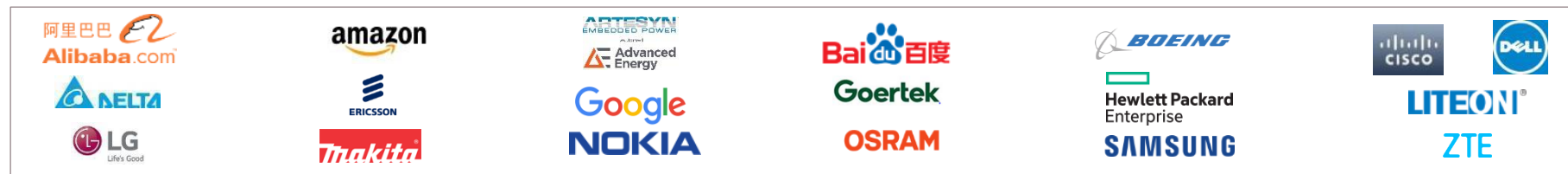
PSS revenue and Segment Result Margin













FY20 revenue split by product group



Key customers



Market outlook for PSS division's target applications

Applications (% of FY20 segment revenue)		Market Outlook for CY21	
<div>Computing</div> <div></div> <div>~20%</div>	<div></div> <div><ul style="list-style-type: none">› Acceleration towards cloud computing to continue› Pandemic-driven stay-at-home and WFH effects continue to favor notebook sales</div>		
<div>Communication</div> <div></div> <div>~9%</div>	<div></div> <div><ul style="list-style-type: none">› In general, long-term drivers due to 5G still intact› However, trade tensions generate some uncertainty around speed of roll-out in China and other regions</div>		
<div>Smartphones</div> <div></div> <div>~19%</div>	<div></div> <div><ul style="list-style-type: none">› Strong rebound expected driven mainly by economic recovery and migration towards 5G phones</div>		
<div>Consumer</div> <div></div> <div>~20%</div>	<div></div> <div><ul style="list-style-type: none">› Consumer electronics, including e.g. game consoles, clear beneficiaries from stay-at-home</div>		
<div>Industrial</div> <div></div> <div>~23%</div>	<div></div> <div><ul style="list-style-type: none">› Automotive and other industrial segments show strong recovery. However, automotive production has taken hits from chip shortages› Battery-powered tools continue to show strong momentum</div>		

* does not sum up to 100% due to other applications not shown here

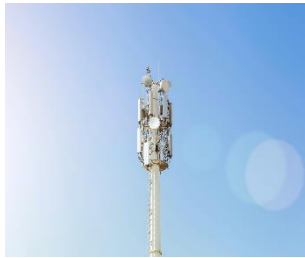
PSS's growth is built on many applications from different sectors in power and non-power

Computing



- › data center
- › enterprise server
- › PC, notebook
- › peripherals
- › chargers and adapters

Communications



- › base stations
- › backhaul cellular infrastructure
- › 5G massive MIMO
- › telecommunication servers

Smartphones



- › smartphones
- › mobile devices
- › wearables
- › USB Type-C, USB Type-C PD

Consumer



- › eBikes, eScooter
- › multicopter
- › LSEV
- › gaming
- › TV sets
- › smart home

Industrial



- › power supplies
- › EV on-board charger
- › charging infrastructure
- › PV inverter
- › power tools
- › lighting
- › Industry 4.0
- › space



PSS – Power

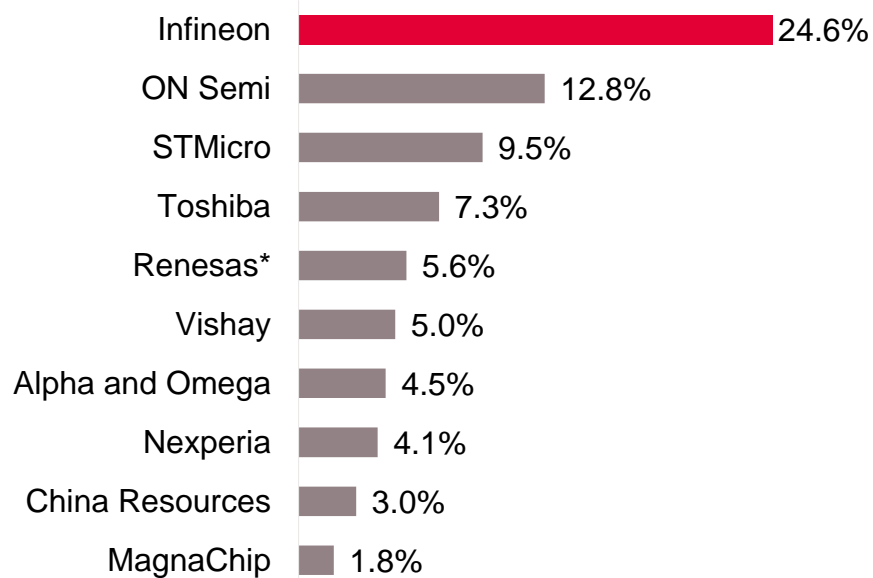


Infineon is the clear leader in MOSFETs; growth potential in power ICs



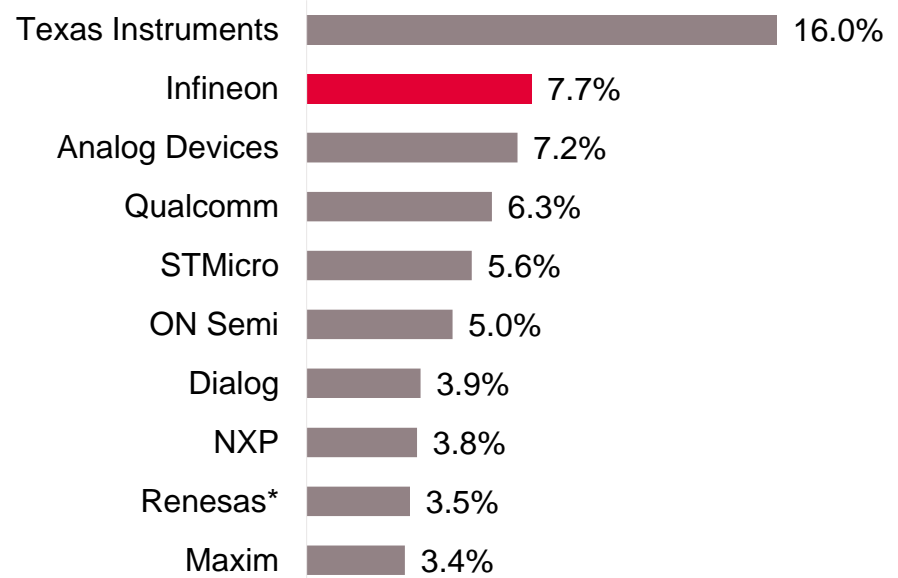
Discrete Power MOSFETs

2019 total market: \$8.10bn



Power ICs

2019 total market: \$24.4bn



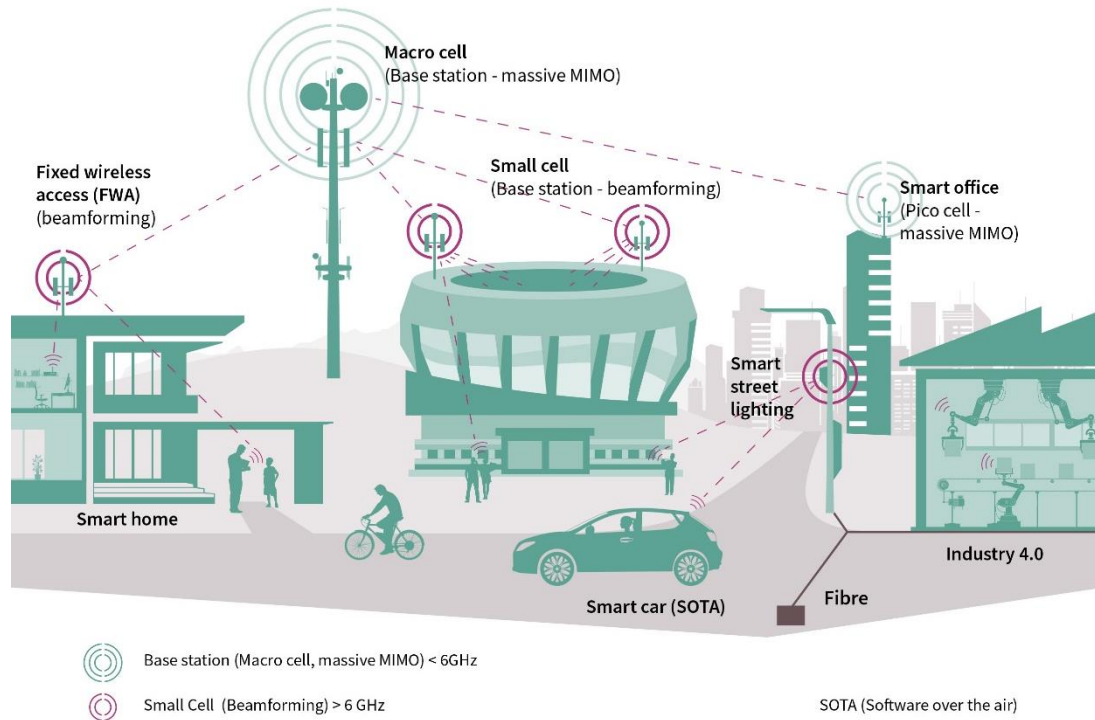
* Renesas acquired Integrated Device Technology in March 2019. Both companies were combined as Renesas in 2019.

Discrete Power MOSFET market includes automotive MOSFETs, protected MOSFETs, SiC MOSFETs and GaN power transistors. Power IC market includes automotive power ICs.

Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020*. September 2020.

Transition from 3G/4G to 5G drives demand in power semis for antennas and power supplies

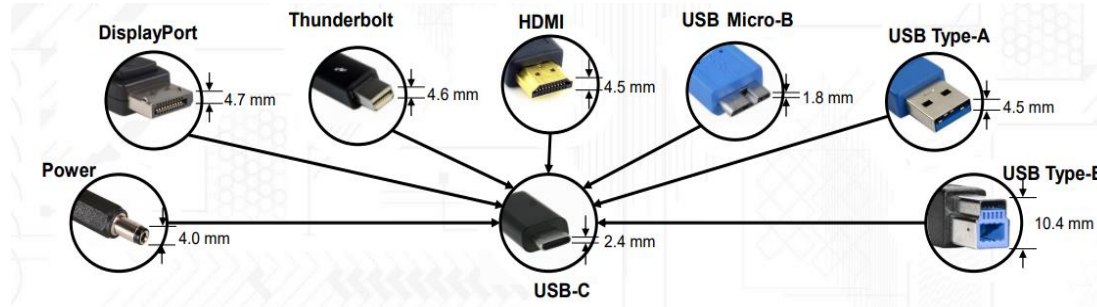
Smart and connected - the communication of tomorrow with 5G



- **driver #1:** massive growth of data and computing power
- **driver #2:** higher number of base stations due to dense network
- **driver #3:** ~4x higher power semi content per radio board: from ~\$25 for MIMO antenna to ~\$100 for massive MIMO antenna array
- **driver #4:** fog computing data center as a completely new market

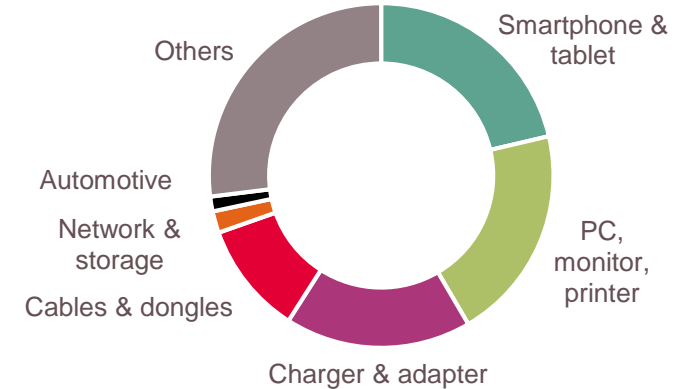
Infinion is well positioned to benefit from the conversion to the de-facto standard USB Type-C

USB Type-C becomes de-facto interface form factor



Infineon USB business split by appl.

[FY20]

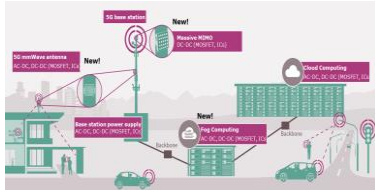


- › Infineon USB business dominated by USB Type-C and USB Type-C PD
- › USB Type-C PD in automotive is a nascent segment with good growth opportunities
- › USB Type-C PD offers revenue synergies for Infineon in AC-DC chargers and adapters

What comes next?

Mid- to long-term structural growth opportunities

Core



5G infrastructure



hyperscale AI data center



new material

Adjacent



smart building



wireless charging



on-board charger

New area



smart speaker



health & lifestyle





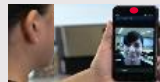

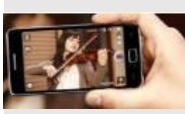
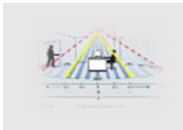


environmental sensor solutions



PSS – RF and Sensing



Main applications addressed by PSS sensors portfolio

MEMS microphone	3D radar (24/60 GHz)	3D ToF image sensor	Environmental
			
Best audio performance	Ultra-low power consumption	Best price / performance	High precision and Small form factor
			
Low power consumption	Presence detection/ Vital Sensing	Face ID (biometrics), VR/AR	Measure CO ₂

Main applications

- › Smartphone
- › True wireless stereo headsets
- › Smart speaker
- › Laptop & Tablet

- › Automotive
- › Smart home
- › TV
- › Security camera
- › Smart building

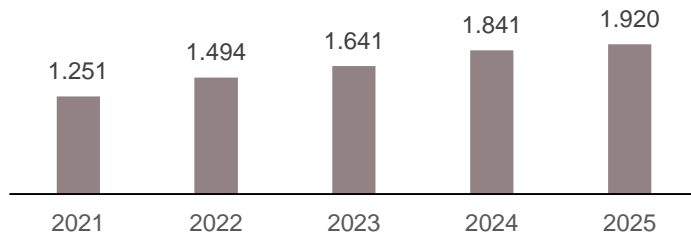
- › Smartphone: world-facing and user-facing
- › Robotics
- › Automotive in-cabin sensing
- › Payment terminals

- › Heating, ventilation, air conditioning (HVAC)
- › Air purifier
- › Smart thermostat
- › CO₂/virus risk reduction

Sensor markets targeted by PSS

MEMS microphone market

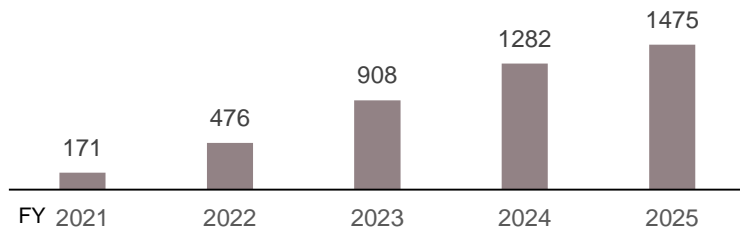
[EUR m]



Source: Infineon estimates

3D ToF image sensor market

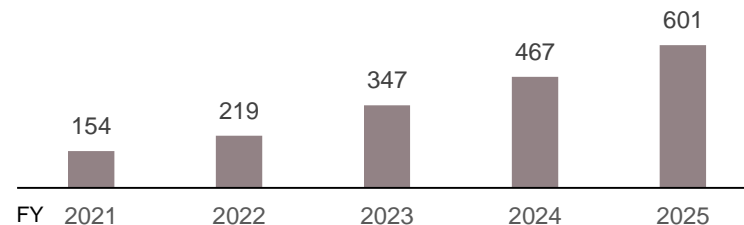
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Source: Infineon estimates

Radar IC market (24 GHz and 60 GHz only)

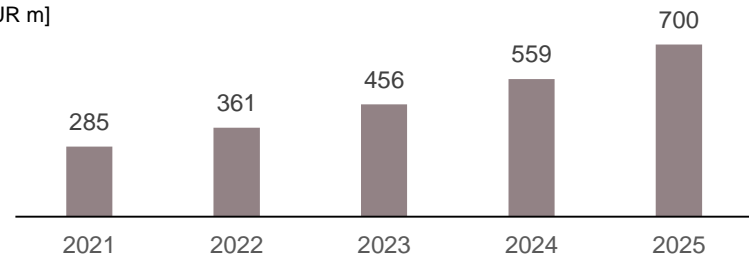
[EUR m]



Source: Infineon estimates

Environmental sensor market*

[EUR m]



* Infineon is addressing smart building, smart home, smart appliances, consumer IoT devices and automotive. Source: Infineon estimates

Different market dynamics of selected PSS sensors

MEMS microphone

- › Strong first quarter and bounce back of the smartphone market in CY 2021 contribute to good MEMS microphone demand growth.
- › Hearables are also a major growth driver. Popular features like active noise cancellation or transparent hearing require 4 to 9 microphones. Traditional wired headsets included only 1 microphone.

3D ToF image sensor

- › Consumer market in non-phone category is showing increasing interest for implementation of 3D ToF cameras in latest electronic equipment. This is driven by applications like service robots, multicopter and AR headsets for education, leisure or medical.

Radar ICs (24 GHz and 60 GHz only)

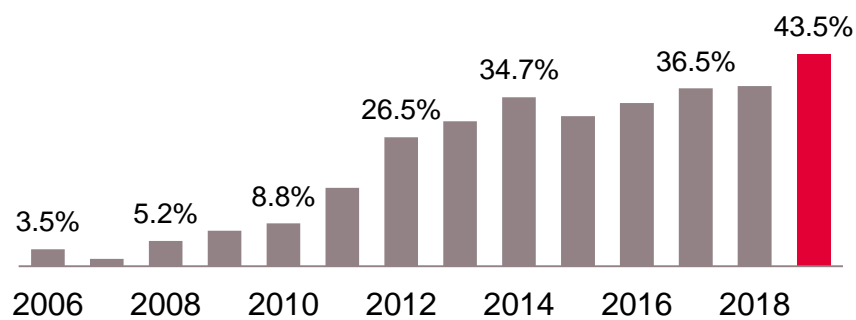
- › Home appliance will drive 60 GHz radar growth in the consumer market (smart lamp, speaker, thermostat a.o.).
- › 60 GHz radar successfully launched as replacement for passive-infrared approach getting traction in the market.
- › New applications like In-cabin-monitoring systems and smart trunk opener will fuel strong growth in automotive.

Environmental sensors

- › Trend for indoor air quality measurement due to health, comfort and energy saving reasons.
- › XENSIV™ PAS CO2 sensor supports reducing the risk of virus transmission by ensuring better and safe indoor air quality.
- › Smart home & smart building market are showing huge interest in usage of CO2 sensors in different applications.

Sweeping success of our XENSIV™ MEMS microphones driven by unparalleled audio characteristics catapulted Infineon to new #1

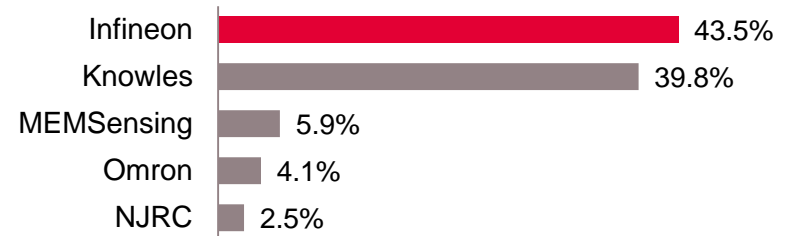
Infineon's market share development in MEMS microphones (by units)



Based on or includes research from Omdia: *MEMS Microphones Dice Market Shares 2020*. October 2020

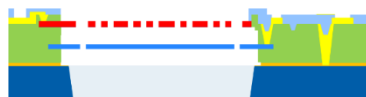
2019 MEMS die market share

total market: 5.4bn units



Technological progression of Infineon XENSIV™ MEMS microphones

1 Single-back plate



SNR = 62 – 65 dB(A)

2 Dual-back plate



SNR = 65 – 69 dB(A)

2014

3 Sealed dual-membrane



SNR = 68 – 75 dB(A)

2019

New 3D ToF image sensor with improved long range to be launched in Q3 FY21

- › Enables functionalities like real-time augmented reality, long range scanning, small object reconstruction, fast low-power autofocus and picture segmentation.
- › Serves applications like gaming, virtual e-Commerce, 3D online education, facial recognition.

Adaptive resolution depending on distance



Characteristics:

- › Long range up to 10 meters
- › High resolution up to 40k depth points
- › Lowest power, reduction of 40% at the imager
- › Accurate and robust depth data under all light conditions
- › Smallest 3D camera; 35% smaller footprint
- › Lowest system BoM due to high integrated CMOS image sensor and Infineon VCSEL driver component

Infineon XENSIV™ PAS CO₂ sensor enables highly-precise CO₂ measuring and will ramp-up for mass market in mid 2021

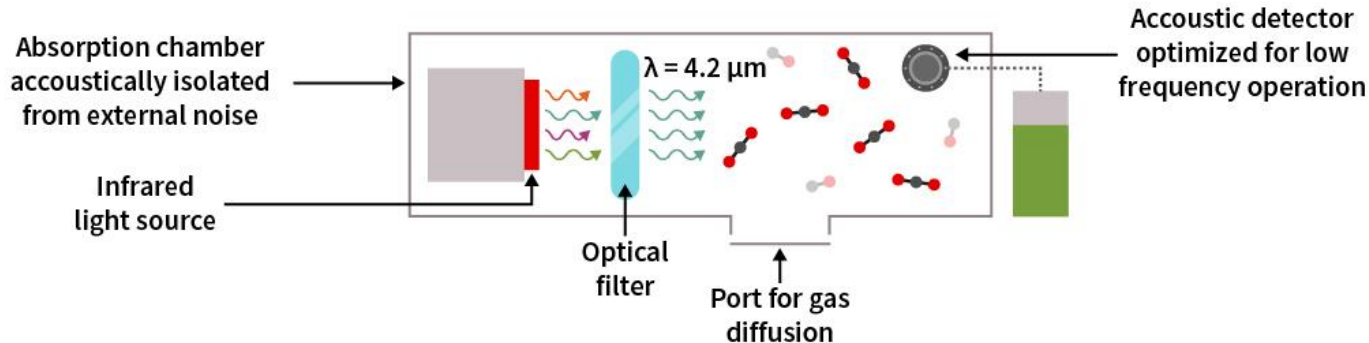


Photoacoustic spectroscopy (PAS) technology based on Infineon's high-sensitivity MEMS microphone

- › Infineon XENSIV™ PAS CO₂ sensor enables highly-precise, cost-effective and space saving CO₂ measuring
- › The technology offers an exceptionally small form factor (14 mm x 13.8 mm x 7.5 mm) that is 4x smaller and 3x lighter (2 grams) than the typical NDIR (non-dispersive infrared) sensor, allowing for more than 75% space savings in customer systems
- › The SMD package ensures compatibility with high-volume manufacturing standards, enabling cost-effective, fast assembly and system integration
- › Advanced compensation and configuration algorithms enable a plug-&-play sensor and fast design-to-market



All XENSIV™ PAS CO₂ sensor components are developed in-house, enabling full control of the system



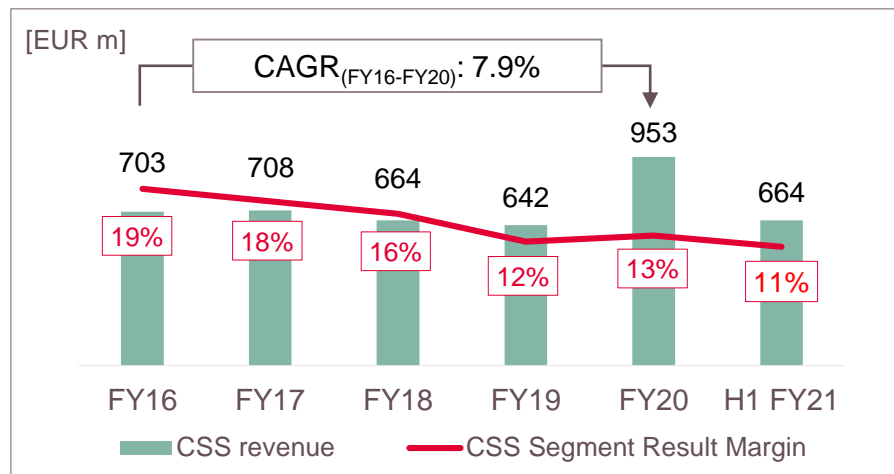


Connected Secure Systems

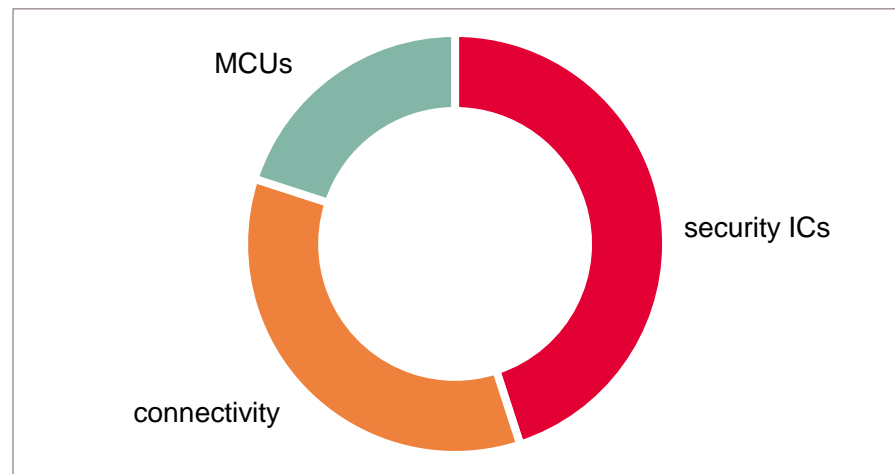


CSS at a glance

CSS revenue and Segment Result Margin

















FY20 revenue split by product group



Key customers



Market outlook for CSS division's target applications – brightening but foundry supply constraints limit upside potential in the near-term

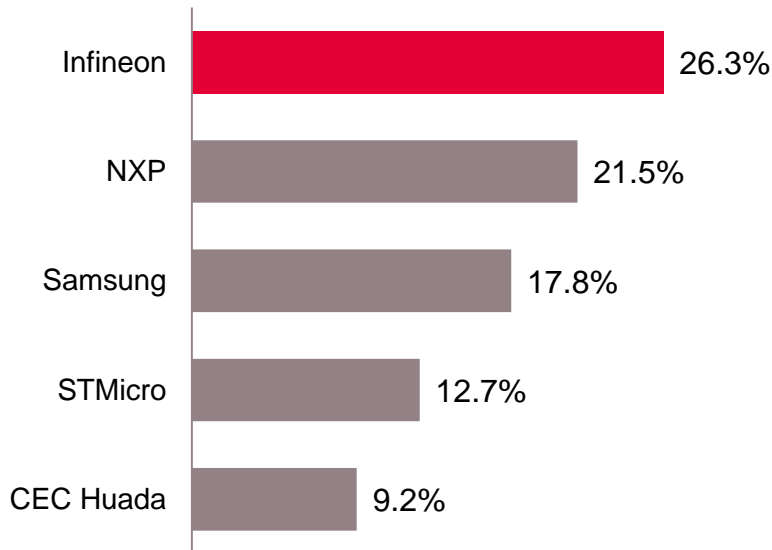
Applications (% of FY20 segment revenue)		Market Outlook for CY21 (not considering supply constraints)	
Industrial and Consumer IoT ~70%			› Growth driven by general market recovery in industrial automation and energy efficiency incentive programs for home appliances
			› New features and technologies enter production and proliferate across several devices
			› Increasing penetration rate of eSIM Automotive driven by increasing connectivity requirements › Connectivity technologies to improve in-car user experience
			› Market growth driven by launch of new console models
			› New product launches expected to boost demand › Further implementation of low-power processing and connectivity technologies across new models
Payment, ID, Ticketing ~30%			› High demand for contactless payment solutions expected to continue
			› Prolonged restrictions on international travel expected to further affect the issuance of passports, partially compensated by a major eID project roll-out

Infineon remains top player in its target markets: security ICs, Wi-Fi standalone ICs



Security ICs (excl. NFC controller; excl. NFC eSE)

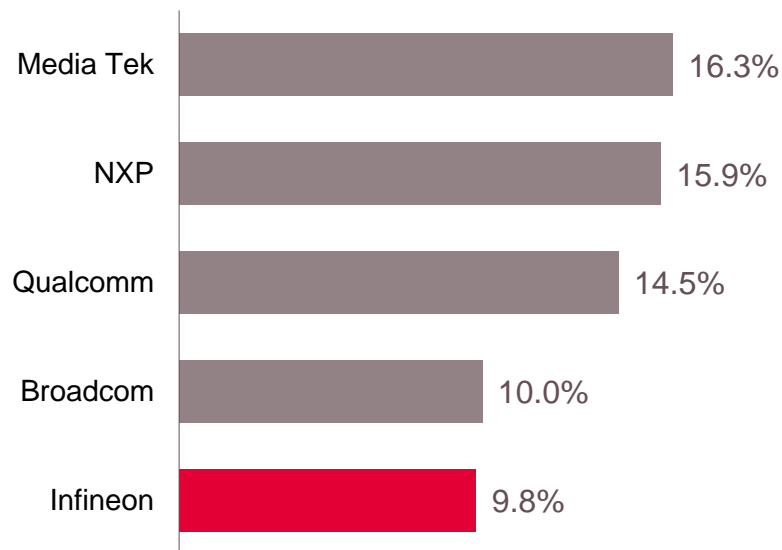
2019 total market: \$2.8bn



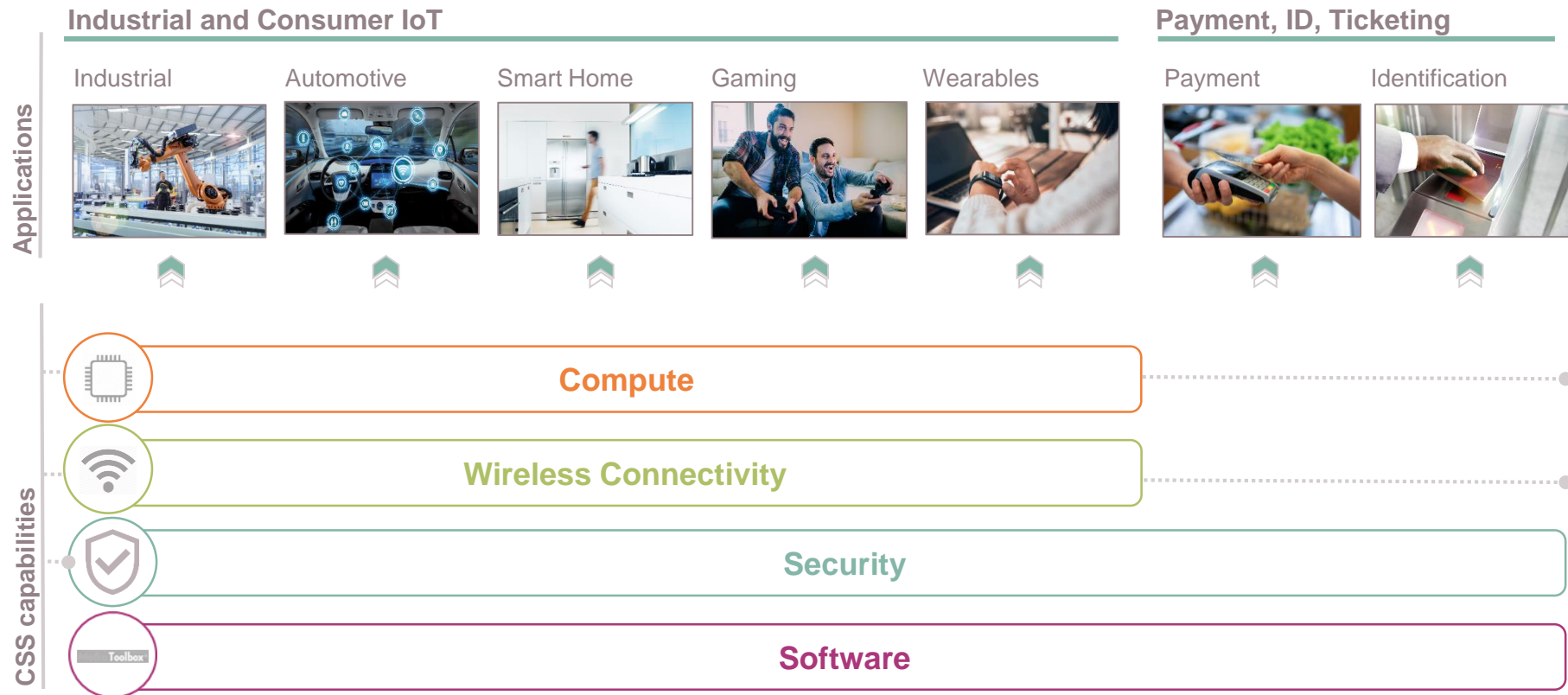
Wi-Fi standalone ICs

2019 total market: 978m units

Infineon is focusing on wearables and IoT but not addressing routers, PCs, notebooks, tablets.

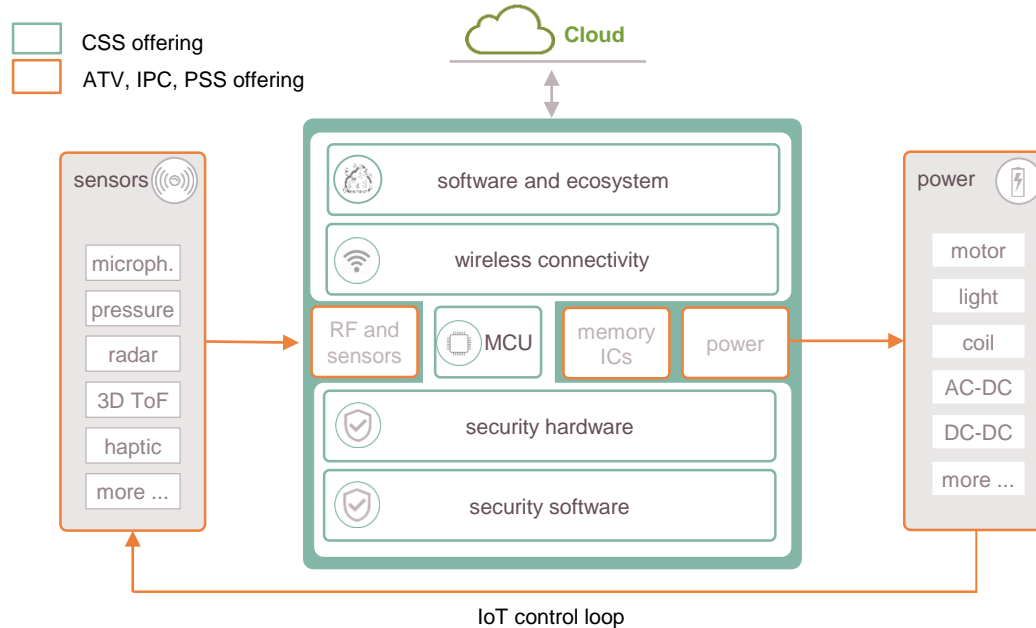


CSS empowers the world to easily connect through smart and trusted solutions

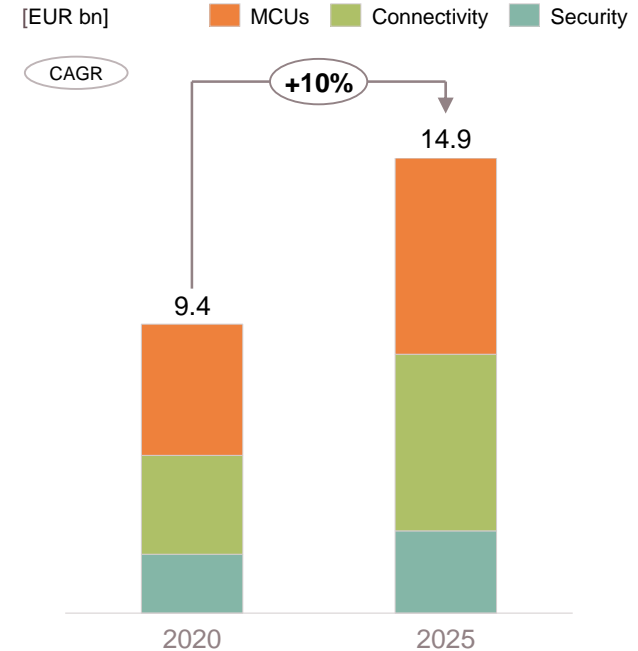


Compute, connectivity, security and software ecosystem capabilities enable Infineon to address a growing market driven by the IoT

Infineon offers the entire system for IoT



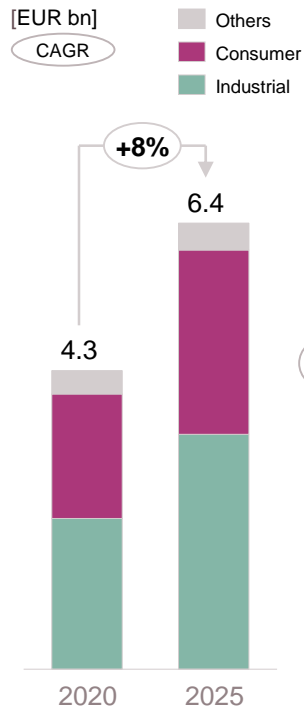
CSS market*



* Source: Infineon internal market model based on SAM view

MCUs – Dynamic market environment; CSS is well set to tackle trends in IoT & Consumer as well as Industrial markets

MCU market*



Trends in MCU markets



Continued growth of MCUs in smart home, driven by home automation devices and wearables



Industrial MCUs growing across wide range of applications



Blurring cost/performance differences between MCUs and MPUs



Beginning to embrace 32-bit MCU with machine learning (ML) acceleration for edge compute

Segments and focus topics

IoT & Consumer



- › Deliver core IoT blocks (MCU, radios, software) and bundled solutions
- › Pairing of MCU and connectivity
- › Prepare and enable emerging edge compute wave with ML capabilities
- › Leading integrated security features

Industrial



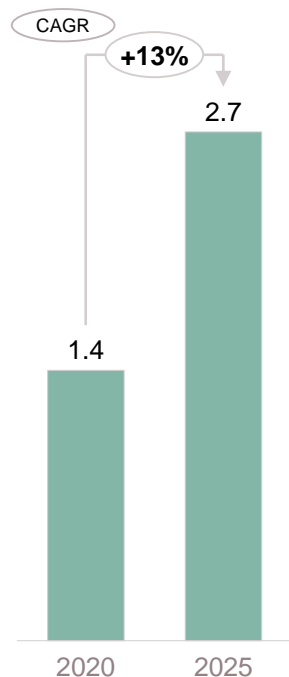
- › Deliver highly differentiated MCU based industrial solutions
- › Provide easy to use sub-system solutions based on Infineon building blocks (sensor control, motor control, power management and connected MCUs)

* Source: Infineon internal market model based on SAM view

Wi-Fi – Market driven by a dynamic environment of specifications; CSS is addressing main growth trends

Wi-Fi market*

[EUR bn]



* Source: Infineon internal market model based on SAM view

Trends in Wi-Fi markets



Specially suited for IoT devices with basic connectivity, low cost, low-power requirements



Focus on high bandwidth IoT applications to ensure data transmission



New standard Wi-Fi 6 is gaining momentum initially on high-performance applications

Segments and focus topics

IoT & Consumer



- › Broad portfolio with Wi-Fi 4 / 5 / 6 standalone and combo offerings
- › Lead transition to Wi-Fi 6 for IoT

IoT low-power



- › Extend leadership on low-power devices
- › System-level power optimization using optimized Wi-Fi product architecture

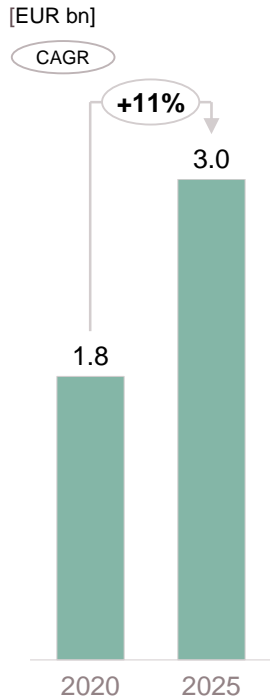
Automotive



- › Extend leadership in automotive infotainment and telematics with Wi-Fi 6 combo offerings
- › Enable enhanced use cases with low-energy audio in auto infotainment

Bluetooth – Market driven by further penetration of Bluetooth use cases across devices; CSS focus topics enable this development

Bluetooth (BT) market* Trends in Bluetooth markets



* Source: Infineon internal market model based on SAM view



Continued growth in smart home, driven by home automation devices and wearables



Covid-19 provides tailwinds for work-from-home electronics and continued digitalization



Shift from Bluetooth single mode and BT/BLE to BLE single mode



LE Audio and Mesh 1.1 are new standards for BT audio and device networks

Segments and focus topics

Smart Home



- › Focus on Mesh 1.1 and Mesh 2.0 (upcoming) device network protocols
- › Drive engagements for emerging standards such as Connected Home over IP

Streaming & Compute



- › Grow BLE-HID (Human Interface Devices) footprint
- › Drive beacons, tags with BLE Location + security in asset-tracking/industrial

Automotive



- › Leverage Infineon Automotive footprint to add auto-body and sensor connectivity
- › Enhance in-cabin experience

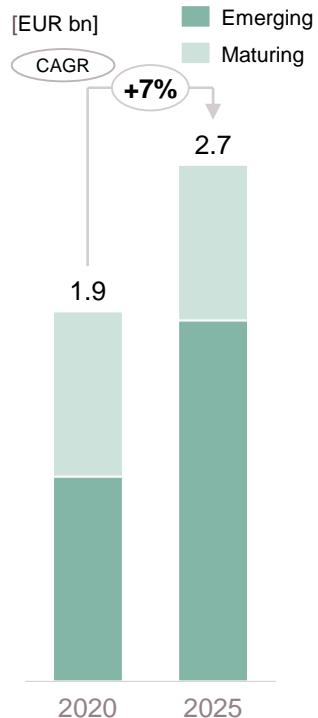
Wearables



- › Infineon Wireless Audio Stereo Synchronization (WASS) in BT speakers as a differentiation
- › Proliferate footprint in wearables by leveraging WASS technology

Security – Several long-term key trends driving value, generating emerging opportunities, shaping CSS' focus in the security field

Security ICs market*



* Source: Infineon internal market model based on SAM view

Trends in security ICs market



Proliferation of contactless payment



Growth of payment-enabled wearables



Proliferation of IoT devices with increased security requirements



Increasing penetration of eSIM Consumer in mobile devices



Anti-counterfeiting for consumer devices to protect end users' health and experience

CSS focus

Innovation leadership

- › Leading silicon technology platforms
- › Contactless performance
- › Secure embedded control

Increasing solution share

- › Enhance full solutions portfolio (silicon + software) with extension of SECORA™ and OPTIGA™ families

Prepare for market opportunities

- › Address adjacent and new market opportunities like biometric cards, wireless charging, new authentication applications, among others

Segments



Payment

Contactless, smart wearables and accessories, biometric cards



Identity

Electronic identification



Ticketing & Access

eTicketing, access management



Device Authentication

Accessories, printer authentication, battery authentication, wireless charging



Mobile Security

eSIM Consumer, SIM



Trust Anchors

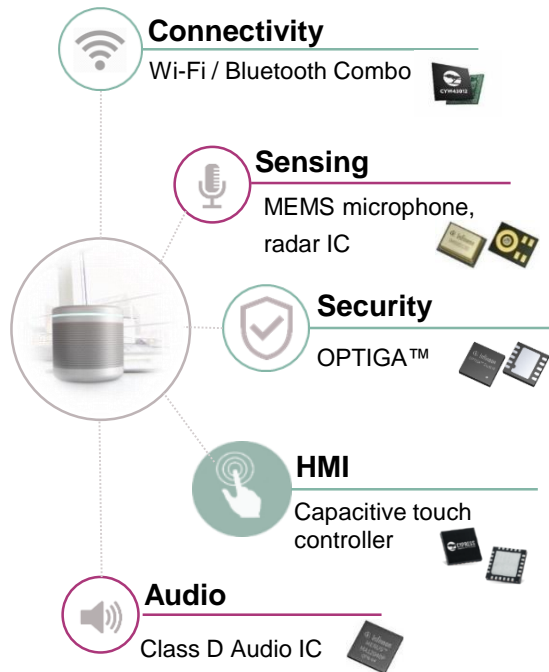
IoT nodes & infrastructure, automotive security

Significant synergy potential of a combined company product portfolio

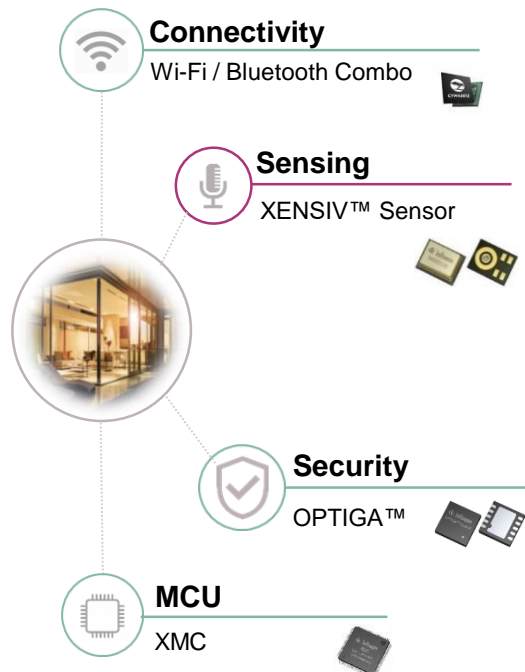
Synergies application examples

 CSS offering
 Other Infineon Divisions offering

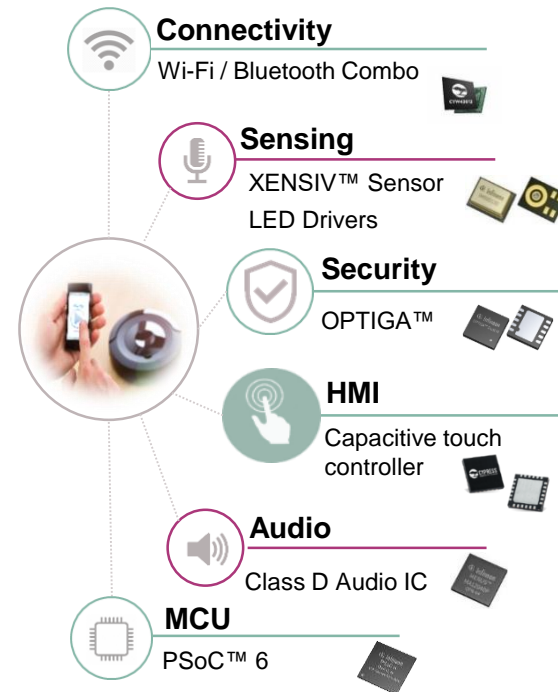
Smart speaker



Smart lighting



Service robots



7RE3	37.278	1.14	+0.72▲	634.270	3.984%	369,000
S421	94.107	0.73	-0.51▼	538.014	2.416%	743,000
YT64	21.744	5.63	+3.16▲	692.360	0.657%	405,000
I897	13.361	1.82	-1.23▼	237.981	0.103%	882,000

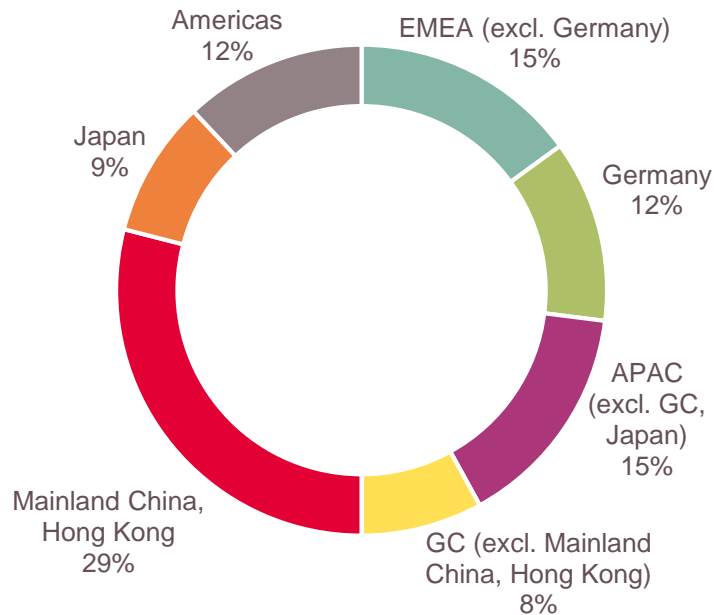


Selected financial figures



Strong presence in all regions; well-balanced customer portfolio;
no customer represents more than 10% of total sales

FY20 revenue by region



Revenue by sales channel*

Distribution and EMS partners

AVX

AVNET

Reach Further

intron

英恒

GET

高捷电子

MACNICA

NEXITY Electronics

RUTRONIK

ELECTRONICS WORLDWIDE

SA

SG

威健

WEIKEN

flex

FOXCONN

Top-10 direct customers

BOSCH

Continental

NELTA

DENSO

HUAWEI

HYUNDAI

SAMSUNG

SIEMENS

THALES

ZF

Distribution and EMS partners

Top-10 direct customers

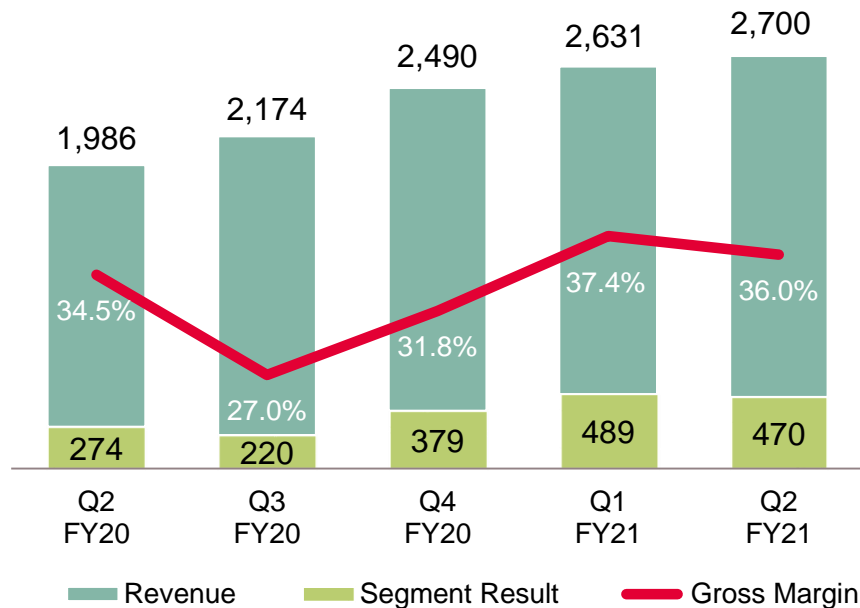
other direct customers

* assuming 12-months revenue contribution of Cypress

Group financial performance

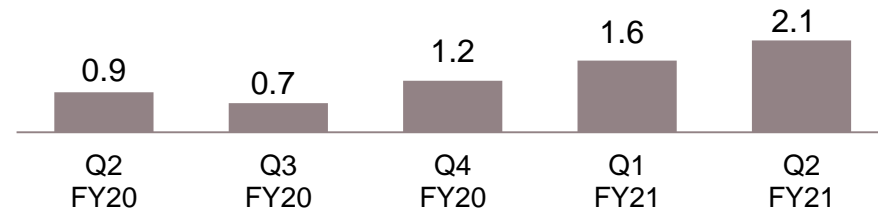
Revenue* and gross margin development

[EUR m]



- › Cyclical dynamics coinciding with a structural upturn
- › Demand is outstripping supply in almost all semiconductor areas
- › Many products are on allocation and inventories are lean
- › Accelerating adoption rates for structural drivers like electro-mobility and IoT

Book-to-bill**

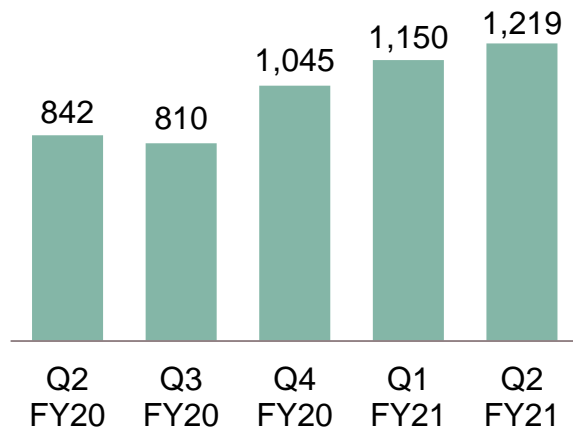


* Consolidation of Cypress revenue as of 16 April 2020. ** For definition see notes

Automotive (ATV)

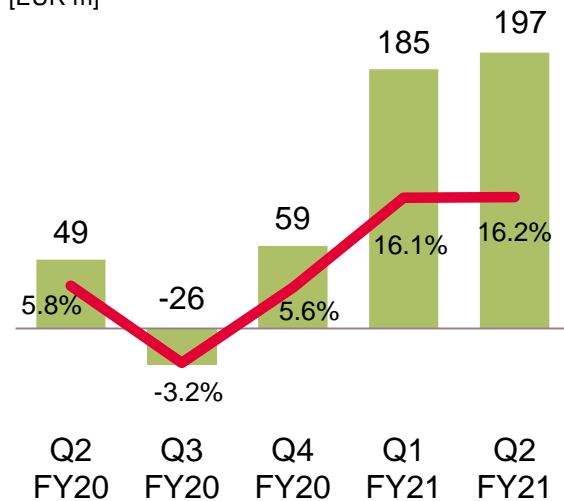
Revenues*

[EUR m]

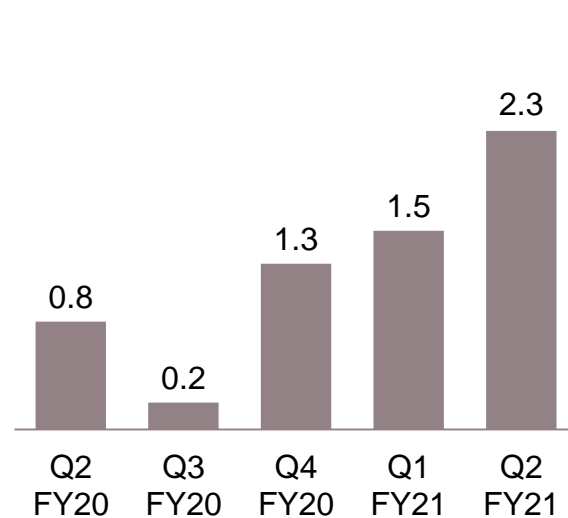


Segment Result*

[EUR m]



Book-to-bill



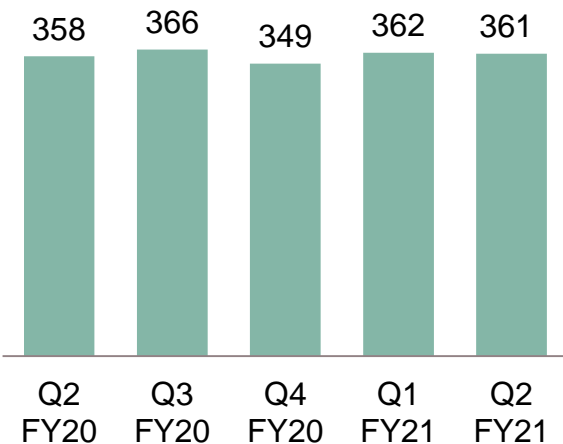
- › Positive revenue contribution from almost all areas - particular strong demand for electric vehicles components
- › Stable margin: negative impacts of Austin power outage and of annual price adjustments compensated by lower underutilization charges
- › Scarce manufacturing capacities, in particular at foundries and subcons, put a speed limit to the automotive recovery.
- › EV and ADAS remain very robust structural trends

* With effect from 1 Oct 2020, we transitioned a group of industrial microcontrollers with an annual sales volume of a low-double digit million Euros from ATV to CSS. Historical figures have been retroactively adjusted.

Industrial Power Control (IPC)

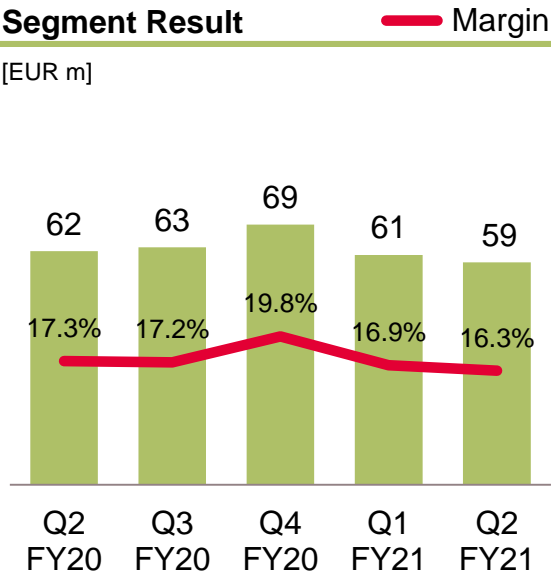
Revenues

[EUR m]

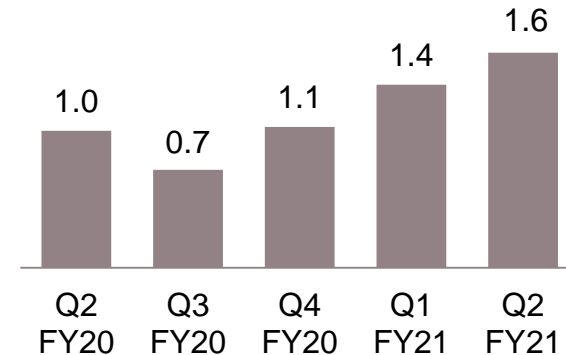


Segment Result

[EUR m]



Book-to-bill

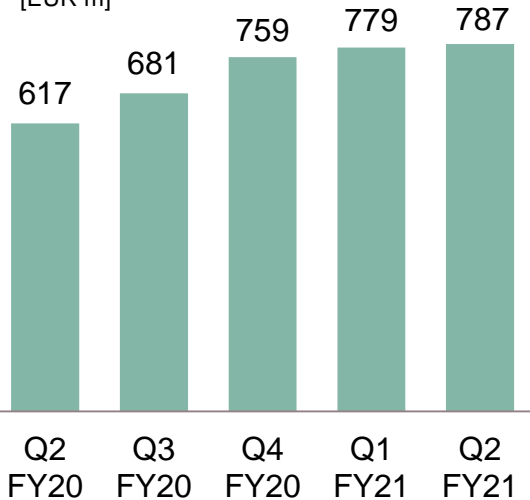


- › Sequential revenue decline in transportation compensated by revenue increases in all other application areas
- › Renewables - positive momentum continues
- › Market conditions for industrial applications continue to brighten
- › Home appliances remain strong, driven by pent-up demand and energy-saving regulations

Power & Sensor Systems (PSS)

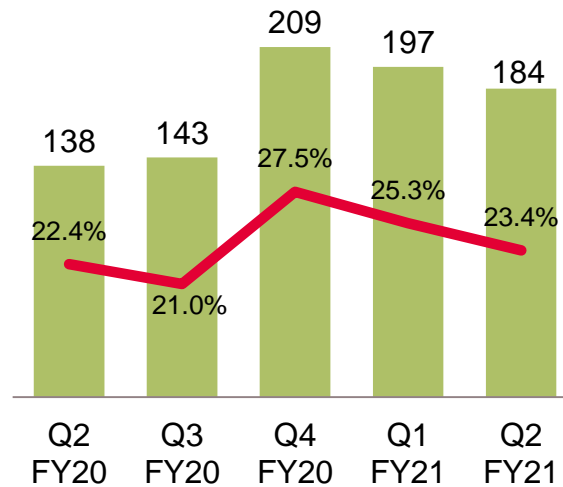
Revenues

[EUR m]

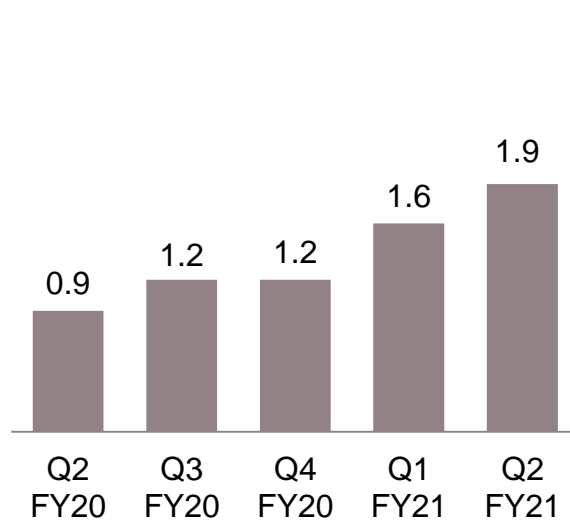


Segment Result

[EUR m]



Book-to-bill

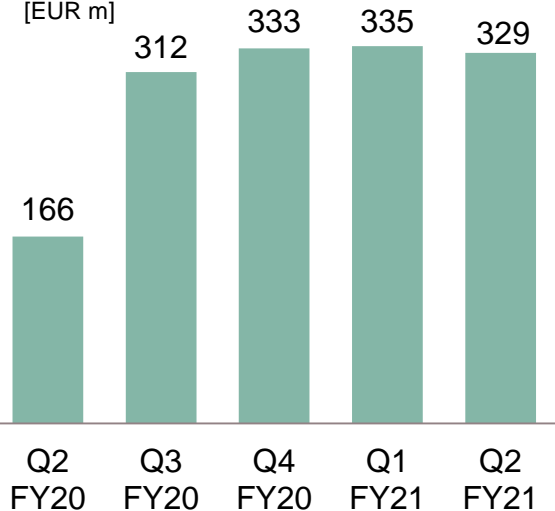


- › Strong demand in multiple end markets, from power tools to telecom servers, overcompensating the seasonal decline in smartphone
- › Supply constraints, in particular from foundries, capped further upside
- › Digitalization leads to disruptive innovations in consumer and industrial applications - smart and “sensorified” devices, edge computing, 5G networks and cloud data centers provide attractive growth opportunities

Connected Secure Systems (CSS)

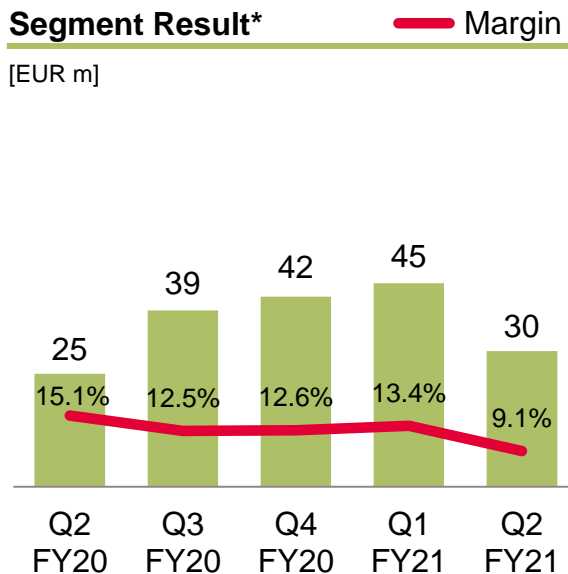
Revenues*

[EUR m]

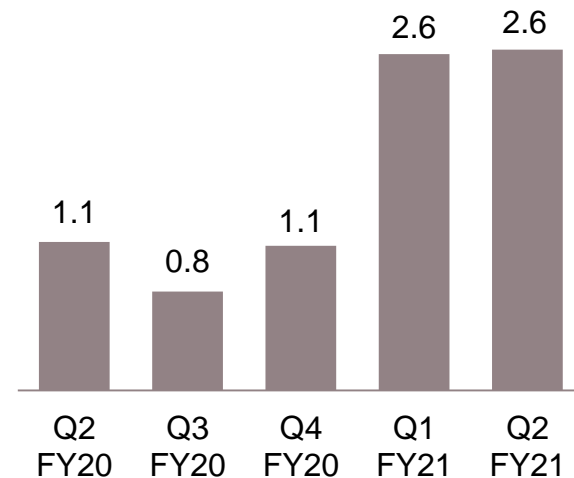


Segment Result*

[EUR m]



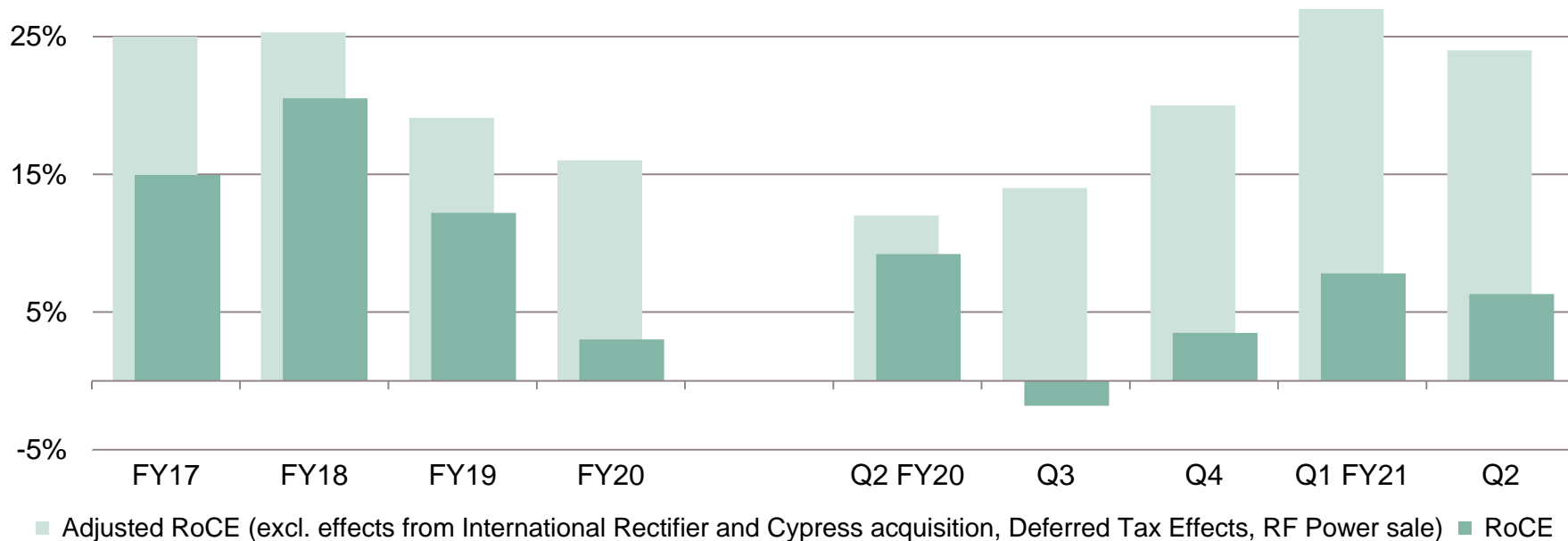
Book-to-bill



- › CSS severely affected by supply constraints - power outage in Austin adds further tightness to the scarce foundry capacities
- › Increased demand for security solutions e.g. contactless payment and device authentication, dampened revenue impact
- › Unabated secular trend towards smart connected devices - vibrant demand especially for general-purpose microcontrollers and connectivity (Wi-Fi/Bluetooth)

* With effect from 1 Oct 2020, we transitioned a group of industrial microcontrollers with an annual sales volume of a low-double digit million Euros from ATV to CSS. Historical figures have been retroactively adjusted.

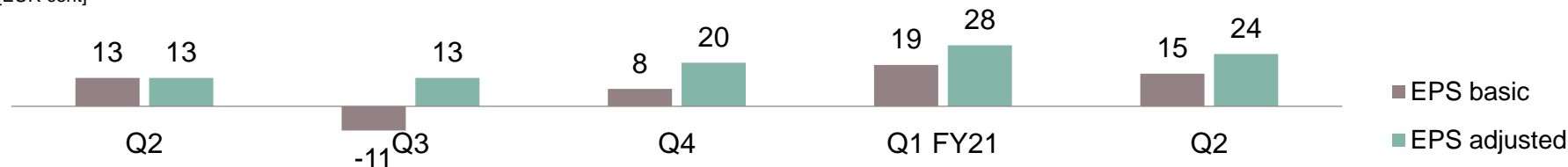
RoCE and adjusted RoCE



Earnings-per-share and total cash return

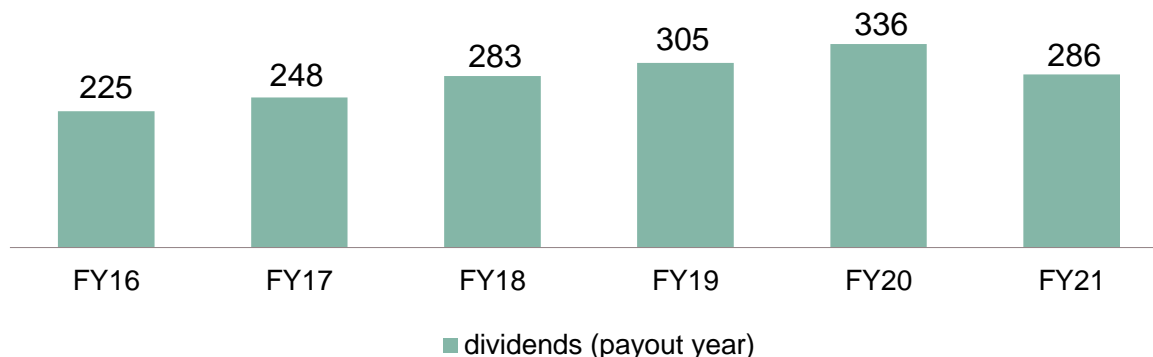
Development of earnings-per-share (EPS) from continuing operations

[EUR cent]



Total cash return to shareholders

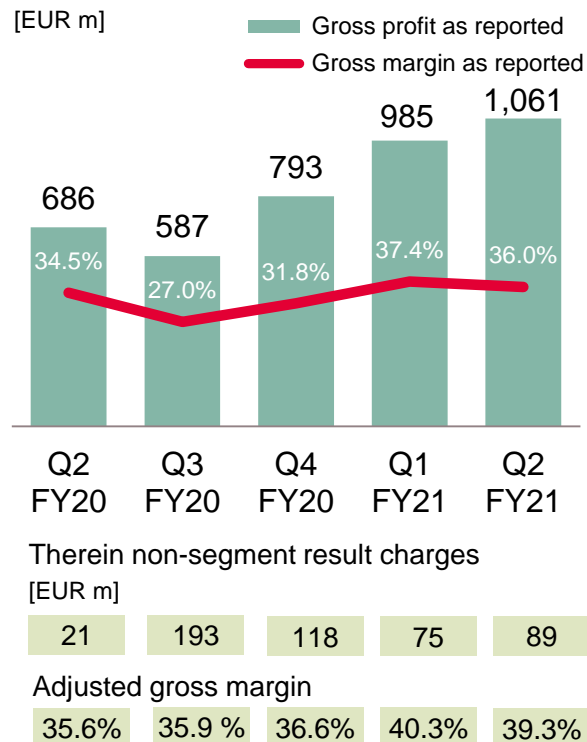
[EUR m]



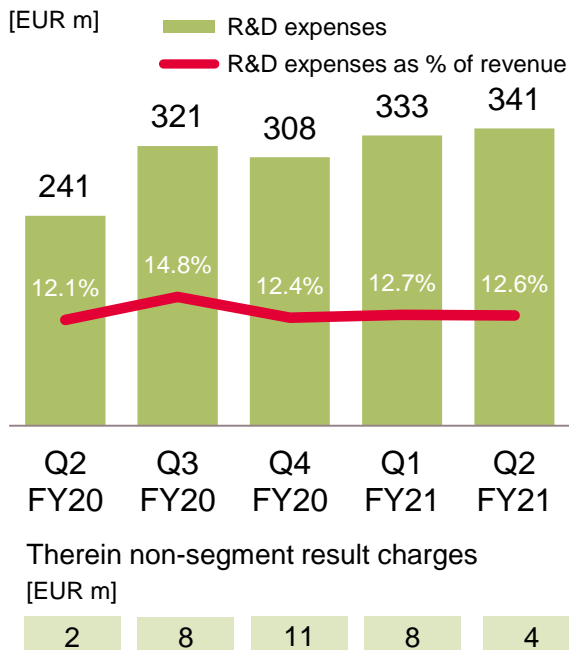
- › Dividend for FY20: €0.22 per share
- › Dividend payout of €286m for FY20 on 2 Mar 2021

Gross margin and Opex

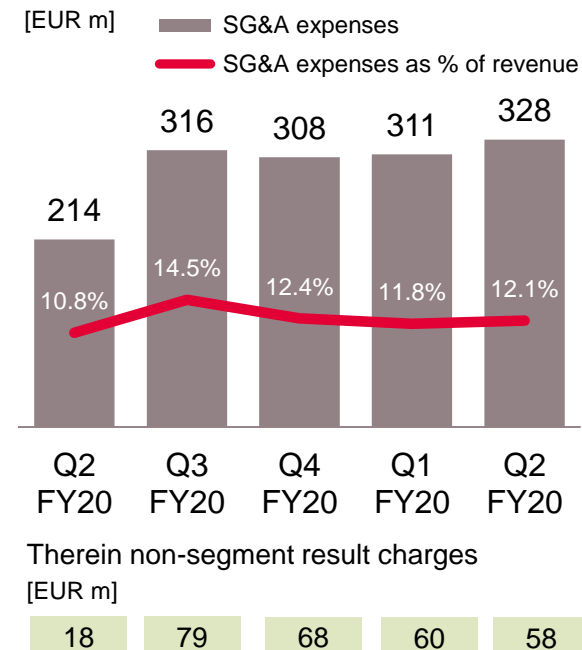
Gross profit



R&D



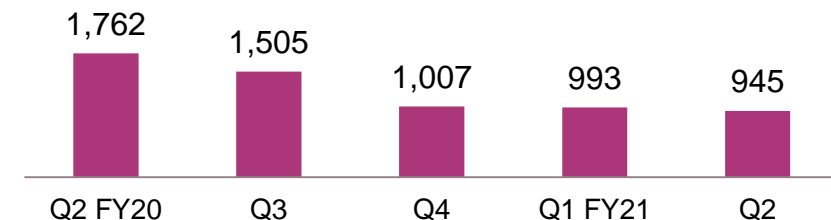
SG&A



Working Capital, in particular trade working capital components

Working capital*

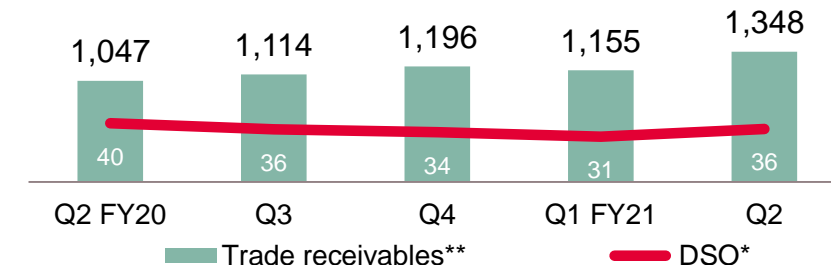
[EUR m]



Trade receivables

[EUR m]

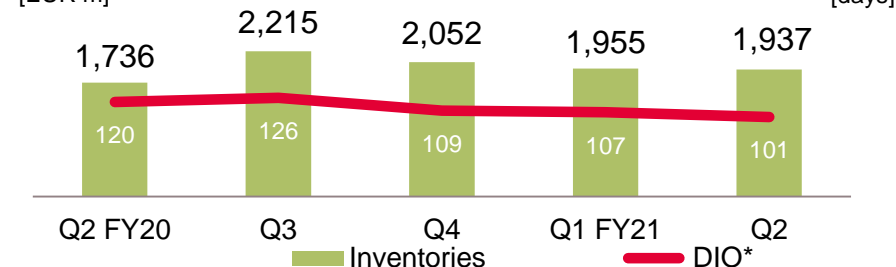
[days]



Inventories

[EUR m]

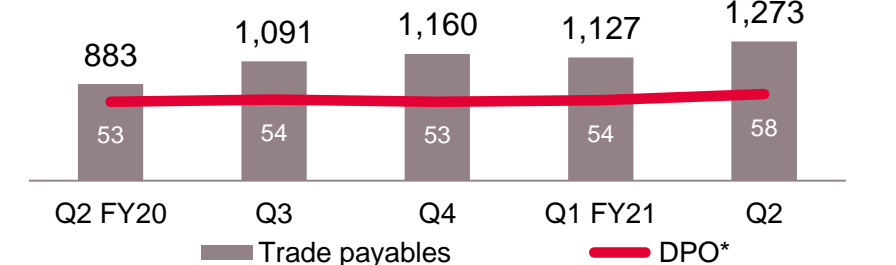
[days]



Trade payables

[EUR m]

[days]



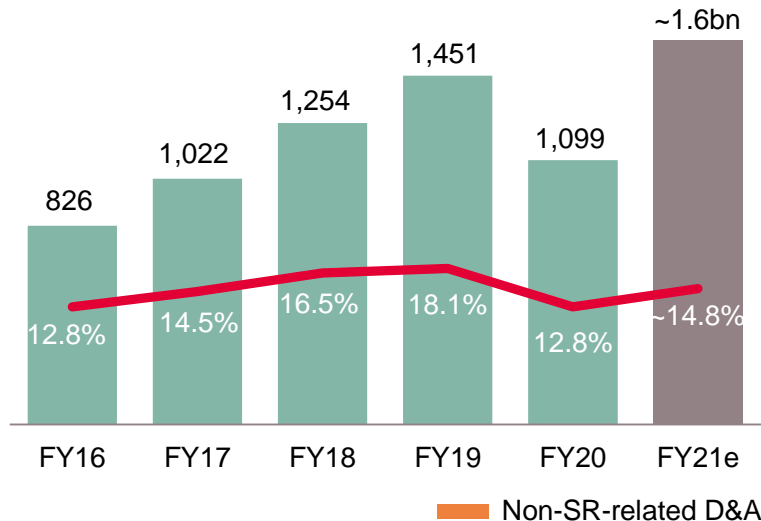
* For definition please see page "Notes".

** Along with the integration of Cypress refund liabilities to customers are presented under "other current liabilities" instead of "trade receivables". Prior quarters' figures were adjusted accordingly for better comparability.

D&A impacted by Cypress consolidation and PPA

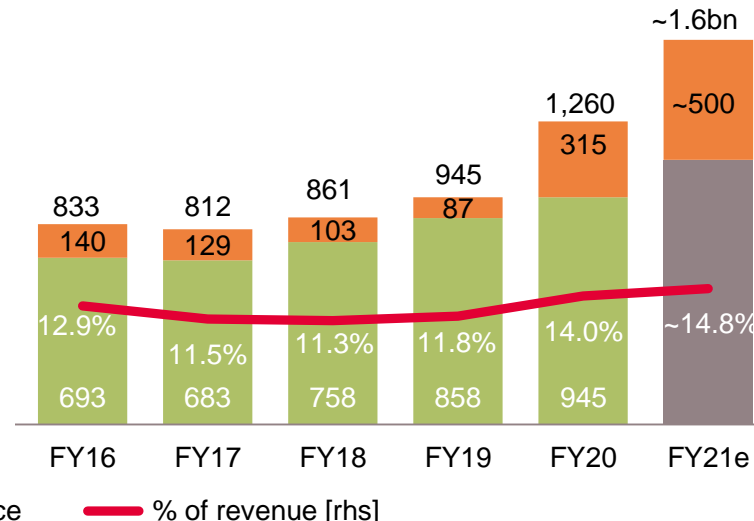
Investments*

[EUR m]



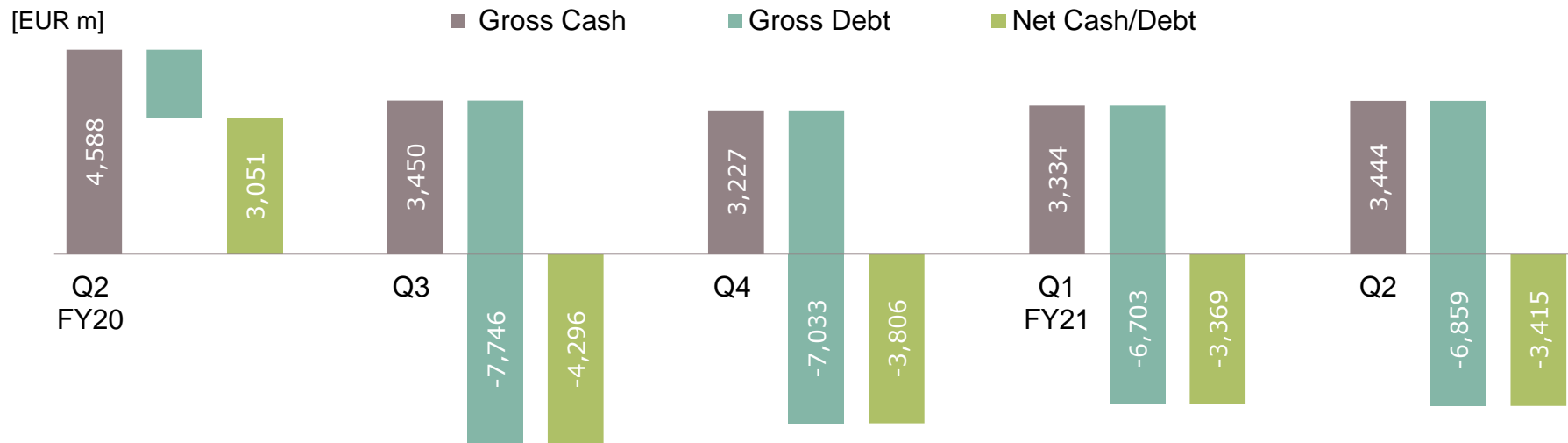
Depreciation & Amortization

[EUR m]



* For definition please see page "Notes".

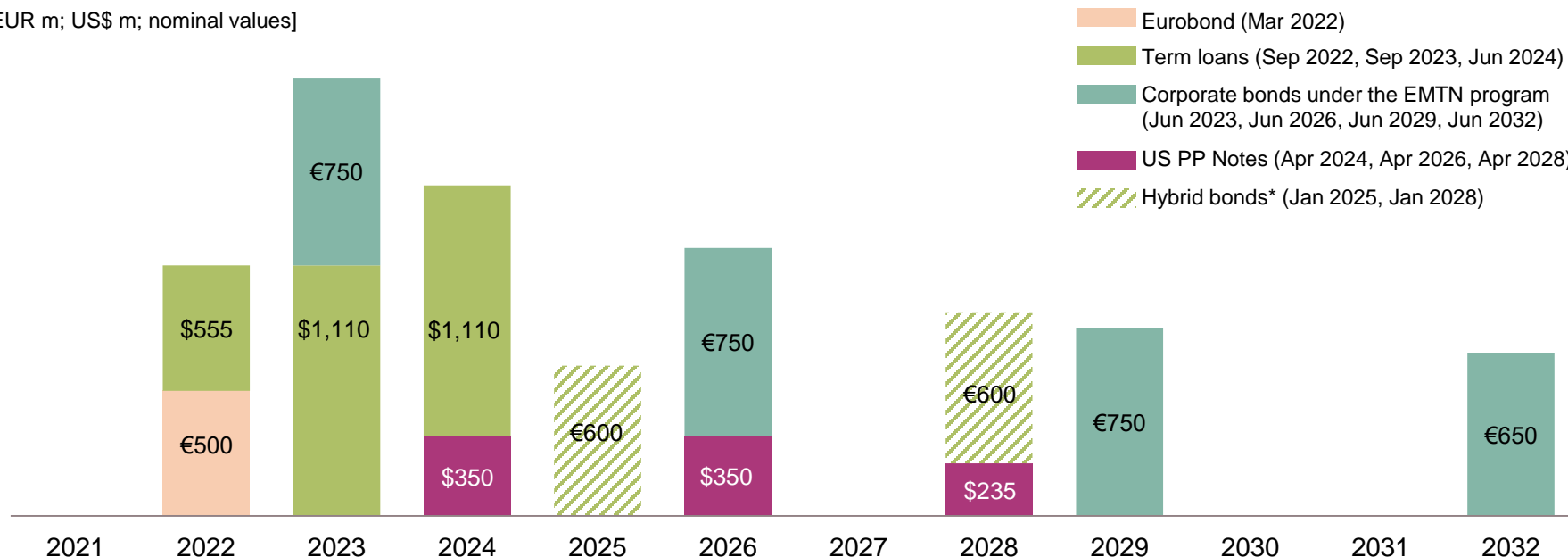
Liquidity development



- › Q4 FY20: early repayment (USD 555m) of bank debt incurred for the Cypress acquisition.
- › Q1 FY21: Gross debt – reduced by 174m EUR repayment and impact of weaker US-dollar on USD-denominated debt.
Net debt: improvement driven by strong free cash flow and, to some extent, currency effects.
- › Q2 FY21: Gross cash increased, as strong free cash flow more than offset dividend payment; gross debt only driven by stronger US-Dollar impacting USD-denominated debt

Maturity profile

[EUR m; US\$ m; nominal values]



Graph excludes pre-existing Cypress convertibles of ~\$382m repayment value, maturing latest 2022, and additional debt with maturities between 2021 and 2023 totaling €9m.

* On 1 Oct 2019, Infineon issued a perpetual hybrid bond with two tranches: €600m with first call date in 2025 and €600m with first call date in 2028; both are accounted as equity under IFRS.



Part of your life. Part of tomorrow.

Glossary (1 of 2)

ABB	accelerated book building
ABS	anti-blocking system
AC	alternating current
AC-DC	alternating current - direct current
AD	automated driving
ADAS	advanced driver assistance system
AEB	automatic emergency braking
AFS	advanced frontlight system
AI	artificial intelligence
AR	augmented reality
ASP	average selling price
BEV	battery electric vehicle
BGA	ball grid array
BLE	Bluetooth Low Energy
BMS	battery management system
BoM	bill of material
BT	Bluetooth
CL	contactless
CPU	central processing unit
CRC	cyclical redundancy check
DC	direct current
DC-DC	direct current - direct current
DIF	dual-interface (contact-based and contactless)
DIY	do it yourself
DPM	digital power management
eCall	emergency call

ECC	error correction code
ECU	electronic control unit
EPS	electric power steering
eSIM	embedded subscriber identity module
ESS	energy storage system
EV	electric vehicle
FHEV	full hybrid electric vehicle
FPGA	field programmable gate array
G2M	go-to-market
GaN	gallium nitride
GPS	global positioning system
GPU	graphics processing unit
HEV	mild and full hybrid electric vehicle
HMI	human machine interaction
HSM	hardware security module
HST	high-speed train
HVAC	heating, ventilation, air conditioning
HW	hardware
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	Internet of Things
IPM	intelligent power module
IVN	in-vehicle networking
iPol	image processing line
IRFPoP	International Rectifier

Glossary (2 of 2)

IVN	in-vehicle networking
LCD	liquid crystal display
LDO	low dropout voltage regulator
LED	light-emitting diode
LSEV	low-speed electric vehicle
LSPS	LS Power Semitech Co. Ltd.
μC	microcontroller
Mb	megabit
MCU	microcontroller unit
MEMS	micro electro-mechanical systems
MHA	major home appliances
MHEV	mild hybrid electric vehicle
MIMO	multiple input, multiple output
micro-hybrid	vehicles using start-stop systems and limited recuperation
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
MOSFET	metal-oxide silicon field-effect transistor
MPU	microprocessor unit
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PAS	photo-acoustic spectroscopy
PFC	power factor correction
PHEV	plug-in hybrid electric vehicle
PMIC	power management IC
Pol	point-of-load
PSoC	programmable system-on-chip

PTC	positive temperature coefficient
PV	photovoltaic
RF	radio frequency
rhs	right-hand scale
Si	silicon
SiC	silicon carbide
SiGe	silicon germanium
SMD	surface mounted device
SMPS	switch-mode power supply
SNR	signal-to-noise ratio
SoC	system-on-chip
SOTA	software over-the-air
SPI	serial peripheral interface
SRAM	static random access memory
SW	software
TAM	total addressable market
TCO	total cost of ownership
ToF	time-of-flight
TPM	trusted platform module
UPS	uninterruptible power supply
USB	universal serial bus
V2X	vehicle-to-everything communication
VR	virtual reality
VSD	variable speed drive
Wi-Fi	wireless fidelity
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

Disclaimer

Disclaimer

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Financial calendar

Date	Location	Event
6 May 2021	Nuremberg → virtual	IPC Business Update Call along with virtual PCIM trade show
19 May 2021	Tarrytown → virtual	Berenberg US Conference
25 May 2021	New York → virtual	3 rd Annual Mizuho Auto Technology Seminar
26 May 2021	Milan → virtual	Equita 16 th European Conference
27 May 2021	London → virtual	JPMorgan European TMT Conference
1 Jun 2021	New York → virtual	Cowen TMT Conference
8 – 9 Jun 2021	Paris → virtual	23 rd Exane BNP Paribas European CEO Conference
10 Jun 2021	San Francisco → virtual	Bank of America Global Technology Conference
16 Jun 2021	Berlin → virtual	dbAccess Berlin Conference
17 Jun 2021	London → virtual	GS European Digital Economy Conference
1 Jul 2021	Barcelona // virtual	PSS Business Update Call along with MWC trade show
3 Aug 2021*		Q3 FY21 Results
1 Sep 2021	Chicago → virtual	Jefferies Annual Semiconductor Conference
2 Sep 2021	Frankfurt → virtual	Commerzbank Corporate Conference
2 Sep 2021	London → virtual	dbAccess European TMT Conference
4/5 Oct 2021	London // virtual	Infineon Capital Markets Day “IFX Day 2021”

* preliminary

ESG footnotes

- 1) This figure considers manufacturing, transportation, function cars, flights, materials, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. and is based on internally collected data and externally available conversion factors. All data relate to the 2020 fiscal year. Manufacturing service providers are not included.
- 2) This figure is based on internally established criteria, which are explained in the explanatory notes. The figure relates to the calendar year 2019 and considers the following fields of application: automotive, LED, induction cookers, server, renewable energy (wind, photovoltaic), mobile phone chargers as well as drives. CO₂ savings are calculated on the basis of potential savings of technologies in which semiconductors are used. The CO₂ savings are allocated on the basis of Infineon market share, semiconductor content and lifetime of the technologies concerned, based on internal and external experts' estimations.
- 3) Calculation based on average polycrystalline photovoltaic cells and the average yearly solar radiation of central Germany.
- 4) Based on the average electricity consumption of private households in Germany and official energy conversion factors.
- 5) Calculation based on average passenger capacity and direct flight route using externally available data and conversion factors.

Notes

Investments = 'Purchase of property, plant and equipment' + 'Purchase of intangible assets and other assets' incl. capitalization of R&D expenses

Capital Employed = 'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')

RoCE = NOPAT / Capital Employed
= ('Income from continuing operations' – 'financial income' – 'financial expense') / Capital Employed

Working Capital = ('Total current assets' – 'Cash and cash equivalents' – 'Financial investment' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')

DIO (days inventory outstanding; quarter-to-date) = ('Net Inventories' / 'Cost of goods sold') x 90

DPO (days payables outstanding; quarter-to-date) = ('Trade payables' / ['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90

DSO (days sales outstanding; quarter-to-date) = ('Trade receivables' - 'reimbursement obligations')* / 'revenue'* x 90

*without debtors with credit balances

Notes

Book-to-bill ratio - Definition

Book-to-bill = Orders received / Revenue in Euro per quarter

- › Orders received contains order backlog and external customer forecast
External customer forecast includes consignment stock forecast by customers
Not included are internal consignment replenishment orders
- › Orders received does not include unconfirmed orders received
Unconfirmed demand will be reported as orders received and in book-to-bill when it gets confirmed
- › Orders received may not coincide with the IFRS 15 definition of a contract with a customer

For further reading

IPC Business Update Call
Dr. Peter Wawer
6 May 2021



<https://www.infineon.com/2021ipccall>

ATV Business Update Call
Peter Schiefer
5 October 2020



<https://www.infineon.com/2020atvcall>

Sustainability Report 2020
23 November 2020



https://www.infineon.com/sustainability_report

CSS Business Update Call
Thomas Rosteck
3 March 2021



<https://www.infineon.com/2021csscall>

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